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Lee et al.

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(54) **MULTIPLE IMPLANT COMMUNICATIONS WITH ADJUSTABLE LOAD MODULATION BASED ON RECEIVED SIGNAL AMPLITUDES**

(58) **Field of Classification Search**
CPC ... A61B 5/0022; A61B 5/0031; A61B 5/7228; A61B 5/0015; A61B 2562/12;
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(71) Applicant: **THE ALFRED E. MANN FOUNDATION FOR SCIENTIFIC RESEARCH**, Valencia, CA (US)

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(72) Inventors: **Edward K. F. Lee**, Fullerton, CA (US); **Harshit R. Suri**, Pasadena, CA (US)

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(73) Assignee: **THE ALFRED E. MANN FOUNDATION FOR SCIENTIFIC RESEARCH**, Valencia, CA (US)

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Primary Examiner — Franklin D Balseca

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(74) *Attorney, Agent, or Firm* — Michael J. Bolan; Vista IP Law Group LLP

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A61N 1/372 (2006.01)

(Continued)

(52) **U.S. Cl.**

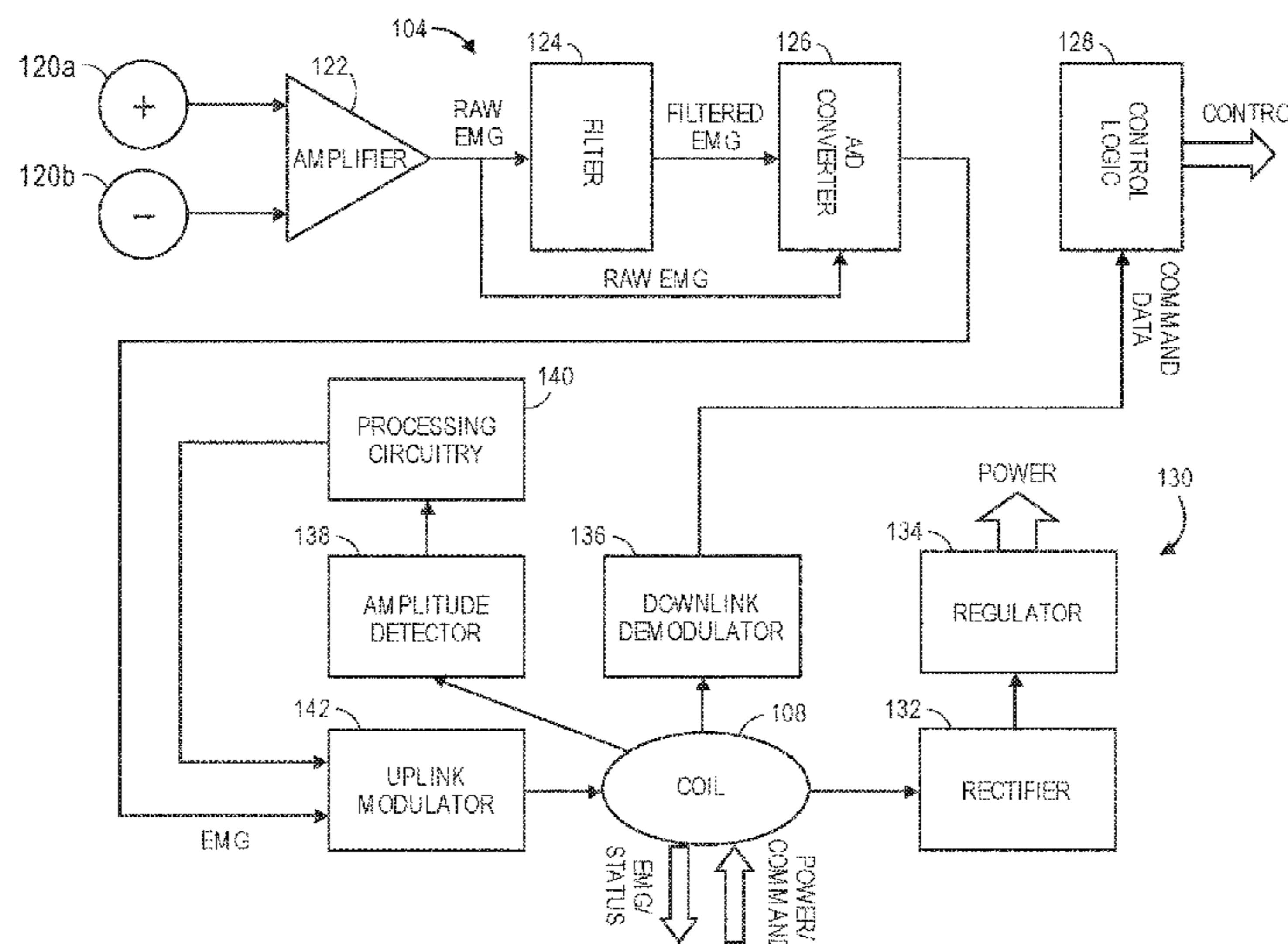
CPC **A61B 5/0022** (2013.01); **A61B 5/0031** (2013.01); **A61B 5/7228** (2013.01);

(Continued)

(57) **ABSTRACT**

A medical system and method of communicating between a telemetry controller and medical devices is provided. Coupling coefficients between a primary coil of the telemetry controller and secondary coils of the medical devices differ from each other. A primary carrier signal is applied to the primary coil, thereby respectively inducing secondary carrier signals on the secondary coils. An amplitude of the secondary carrier signal is measured on each of the secondary coils. The envelope of each secondary carrier signal is modulated in accordance with data, thereby inducing modulation of the envelope of the primary carrier signal for the implanted medical devices. The secondary carrier signal envelopes are modulated based on the measured amplitudes of the respective secondary carrier signals.

24 Claims, 14 Drawing Sheets



Related U.S. Application Data

(60) Provisional application No. 62/456,576, filed on Feb. 8, 2017.

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H04B 14/00 (2006.01)
H04L 27/02 (2006.01)
H04L 27/10 (2006.01)
H04L 27/18 (2006.01)

(52) **U.S. Cl.**
CPC *A61N 1/37288* (2013.01); *A61B 5/0015* (2013.01); *A61B 2562/12* (2013.01); *A61N 1/3727* (2013.01); *A61N 1/37282* (2013.01); *H04B 14/004* (2013.01); *H04L 27/02* (2013.01); *H04L 27/10* (2013.01); *H04L 27/18* (2013.01)

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CPC *A61N 1/37288*; *A61N 1/3727*; *A61N 1/37282*; *H04B 14/004*; *H04L 27/02*; *H04L 27/10*; *H04L 27/18*; *H04Q 9/00*;

H04Q 2209/00; H04Q 2209/40; H04Q 2209/50

See application file for complete search history.

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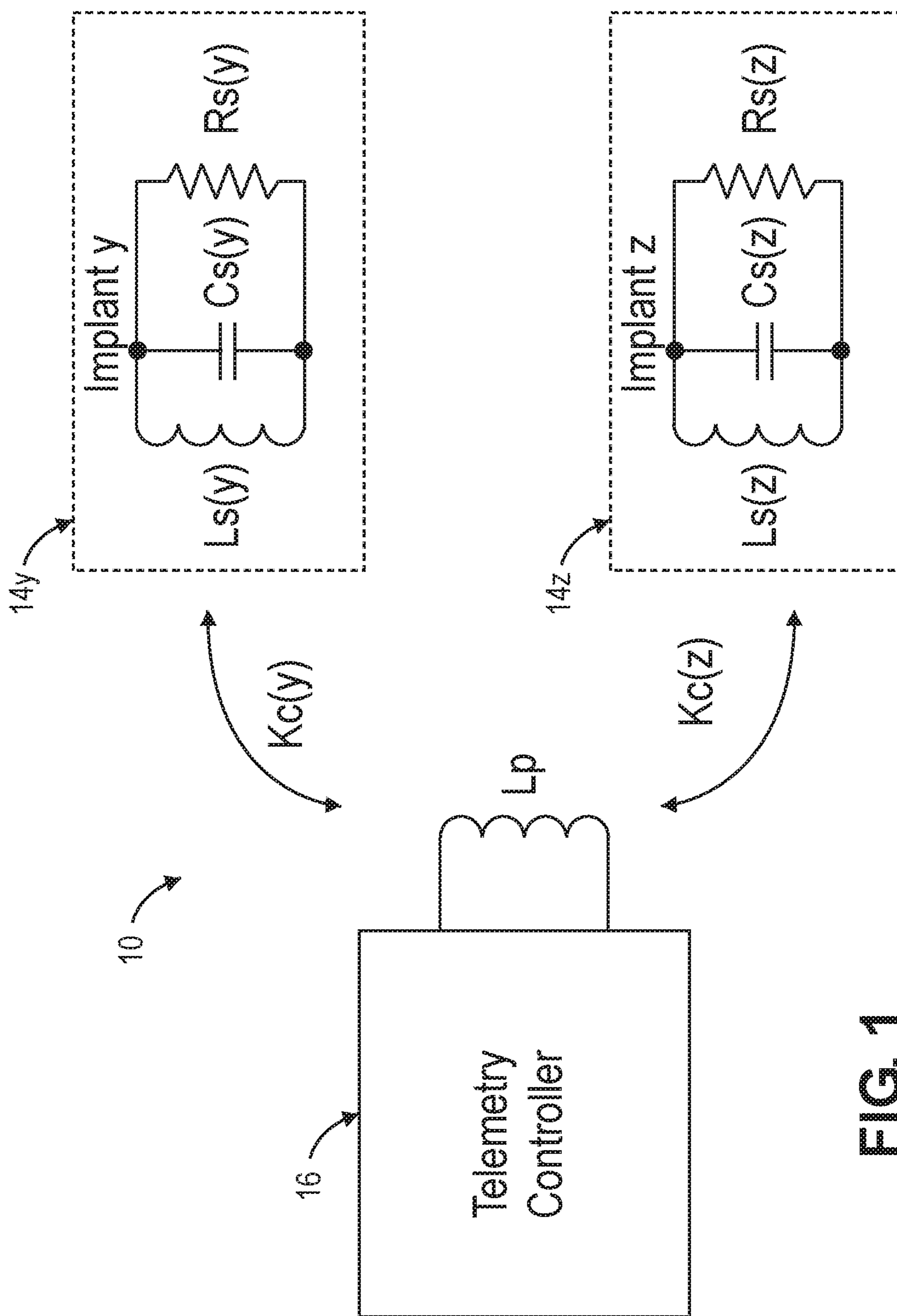


FIG. 1
(PRIOR ART)

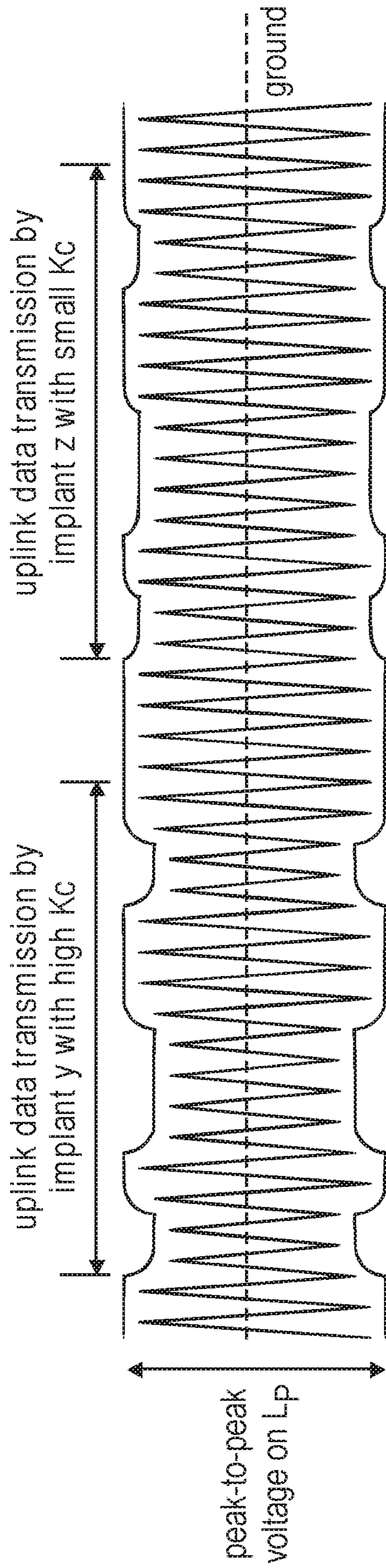


FIG. 2
(PRIOR ART)

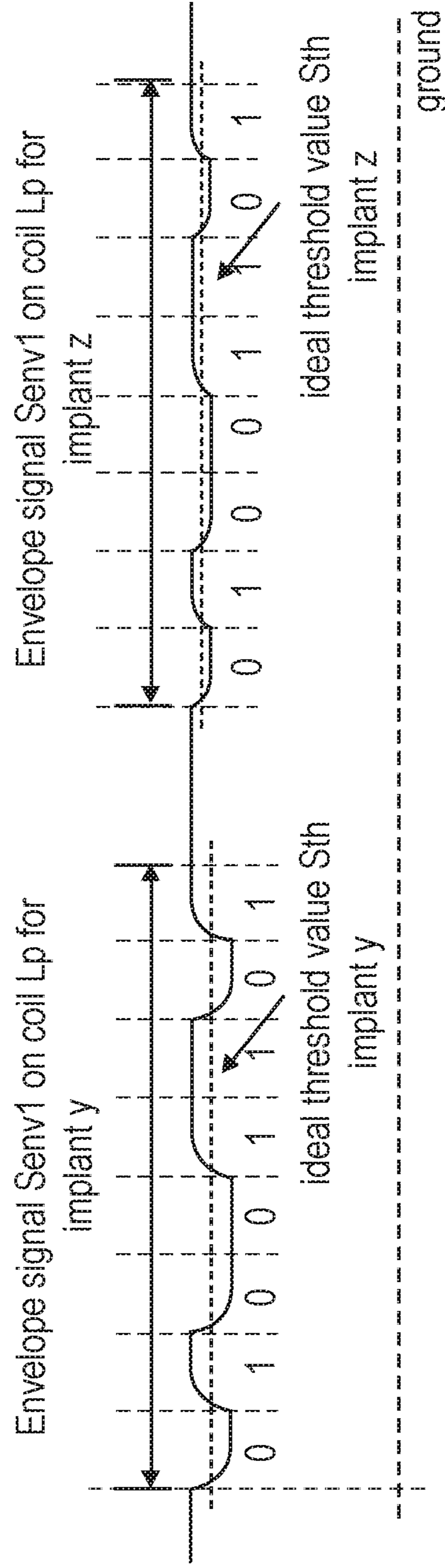
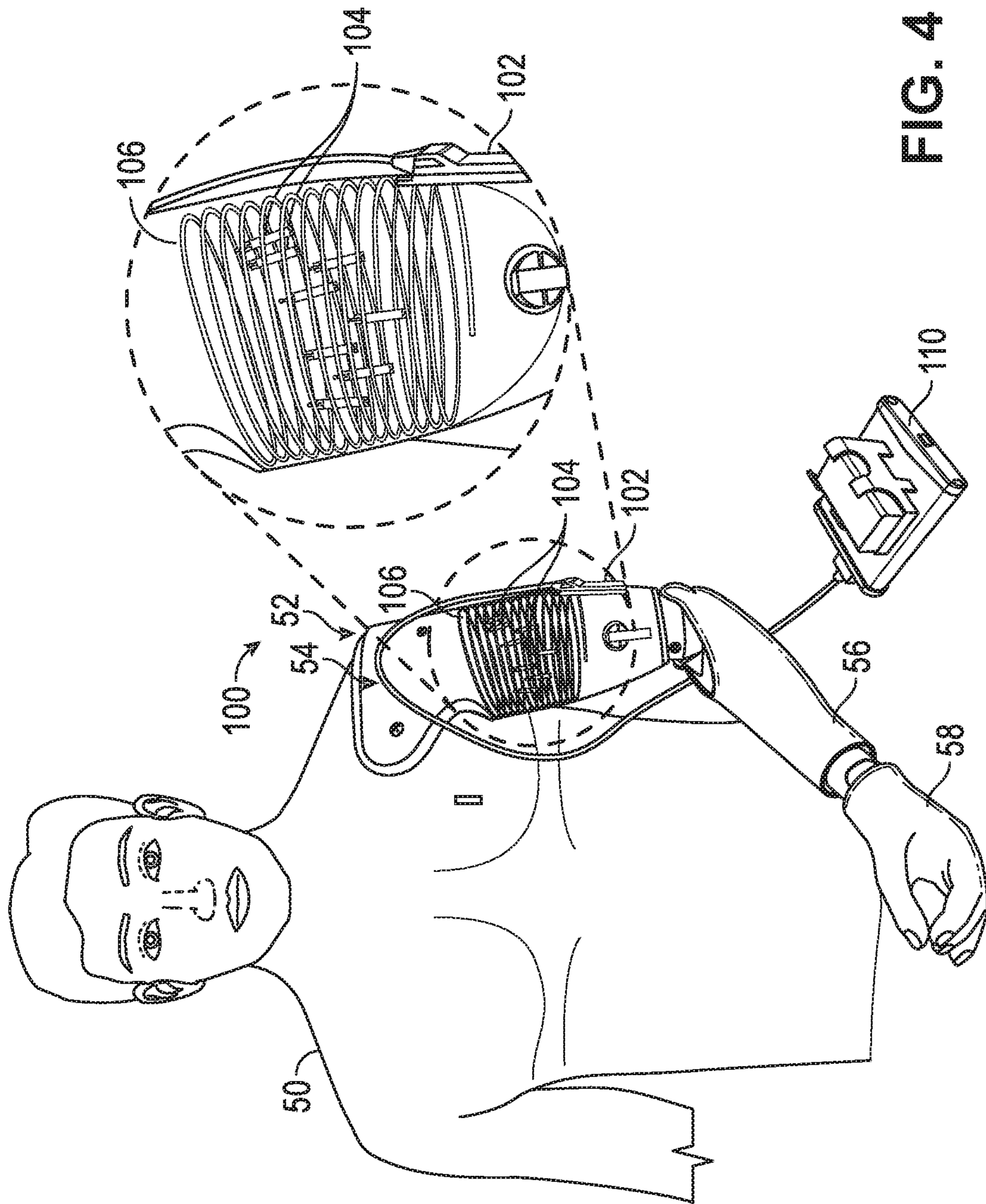


FIG. 3A
(PRIOR ART)



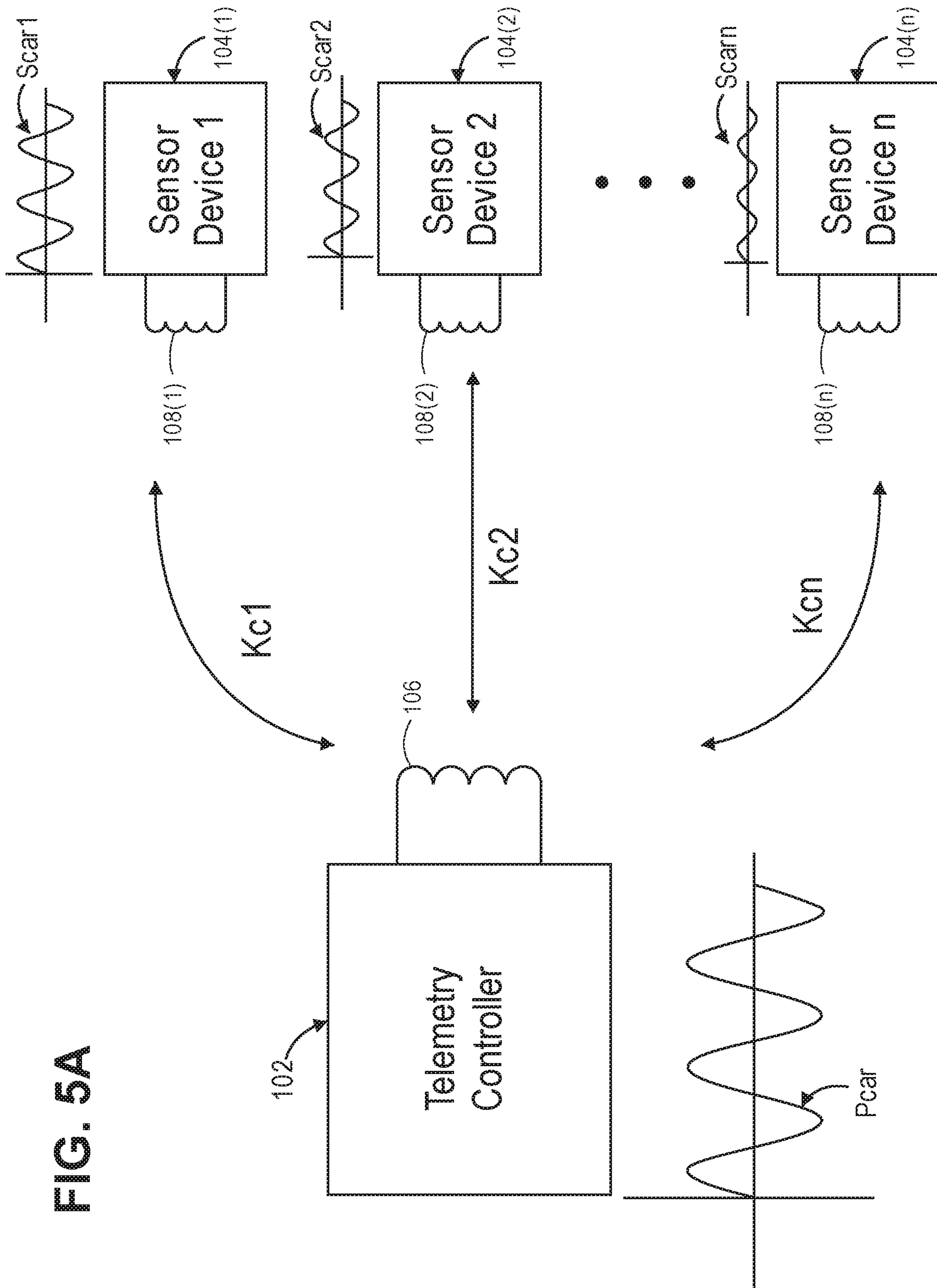


FIG. 5A

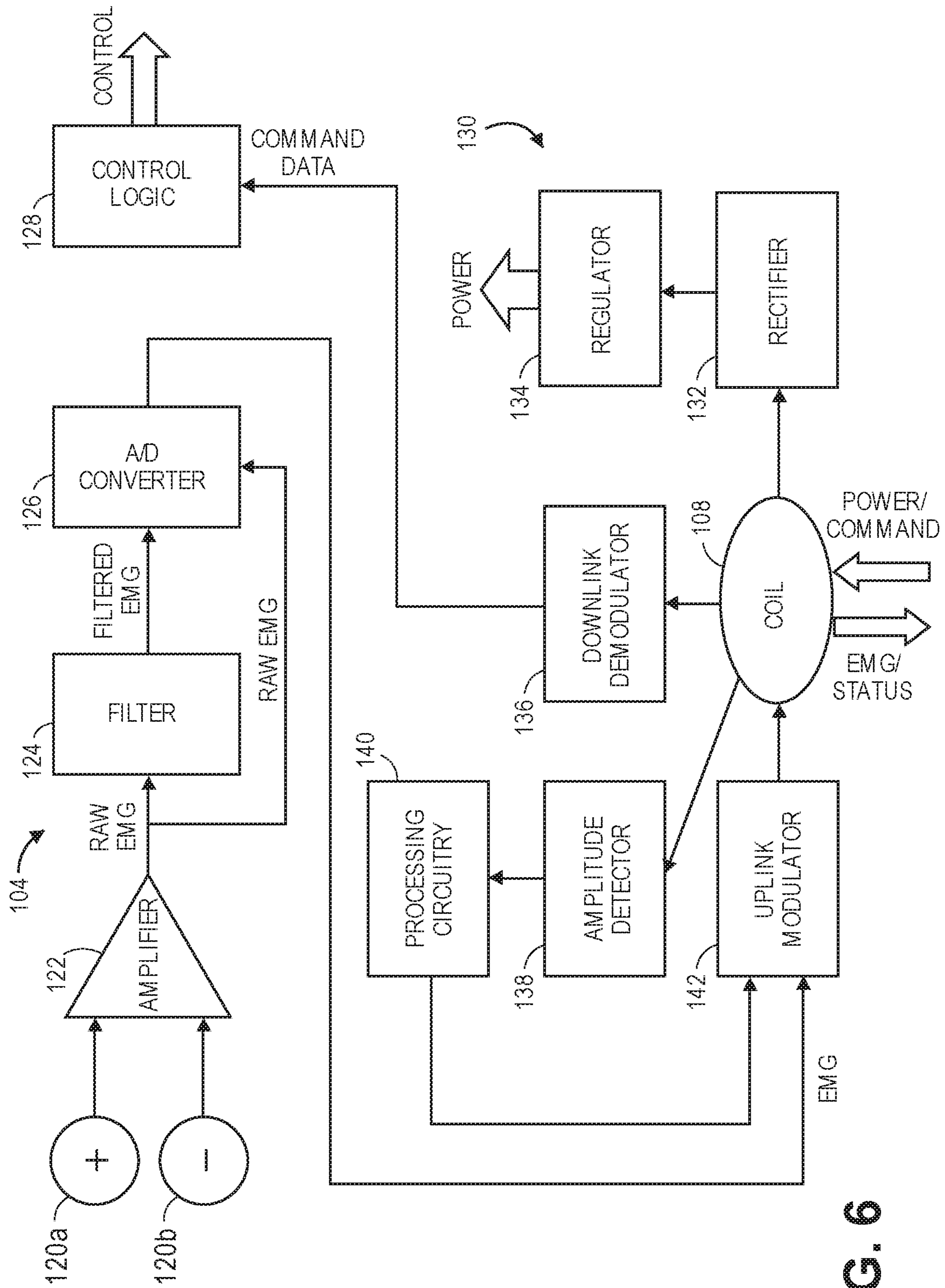


FIG. 6

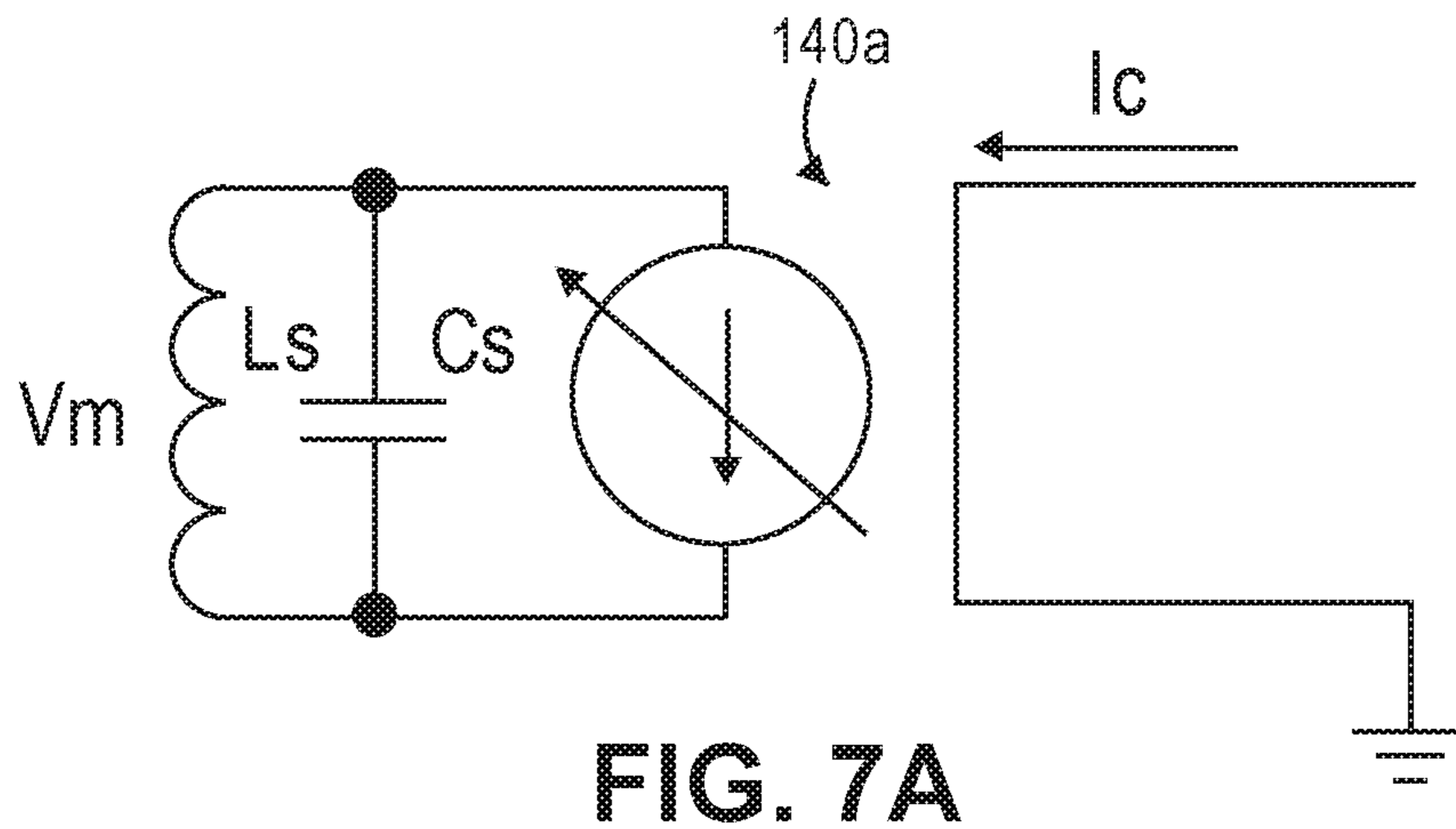


FIG. 7A

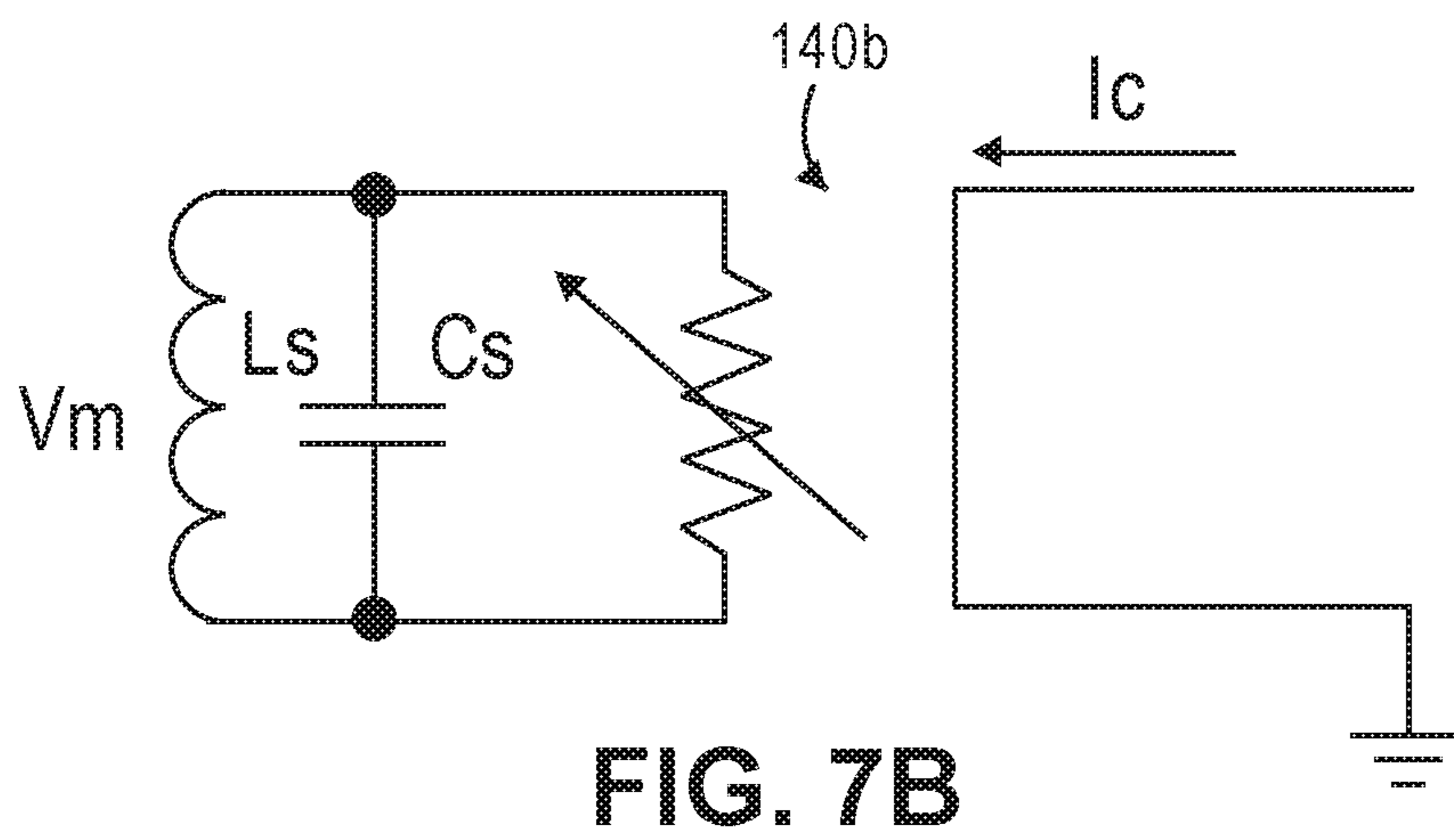


FIG. 7B

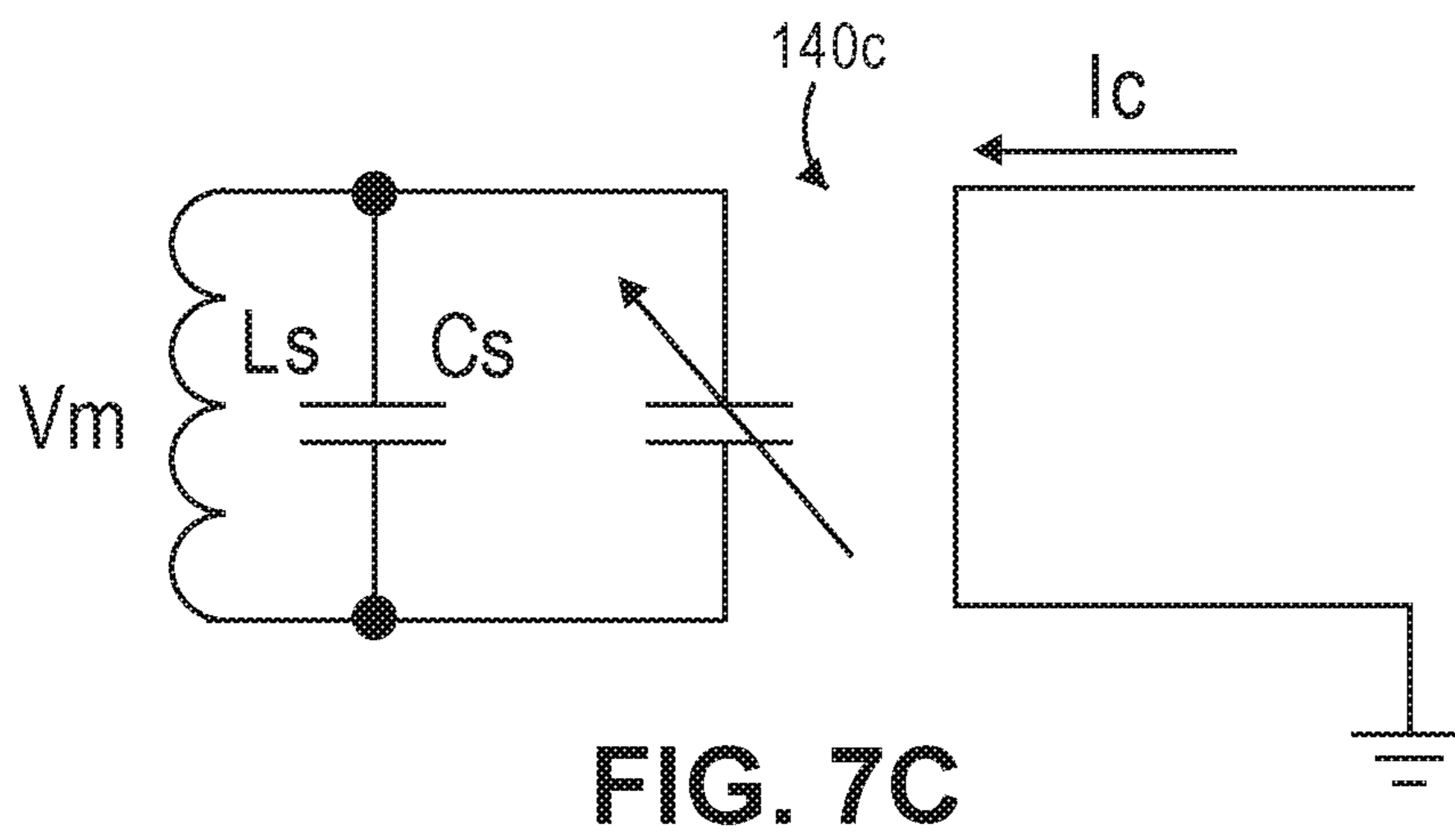


FIG. 7C

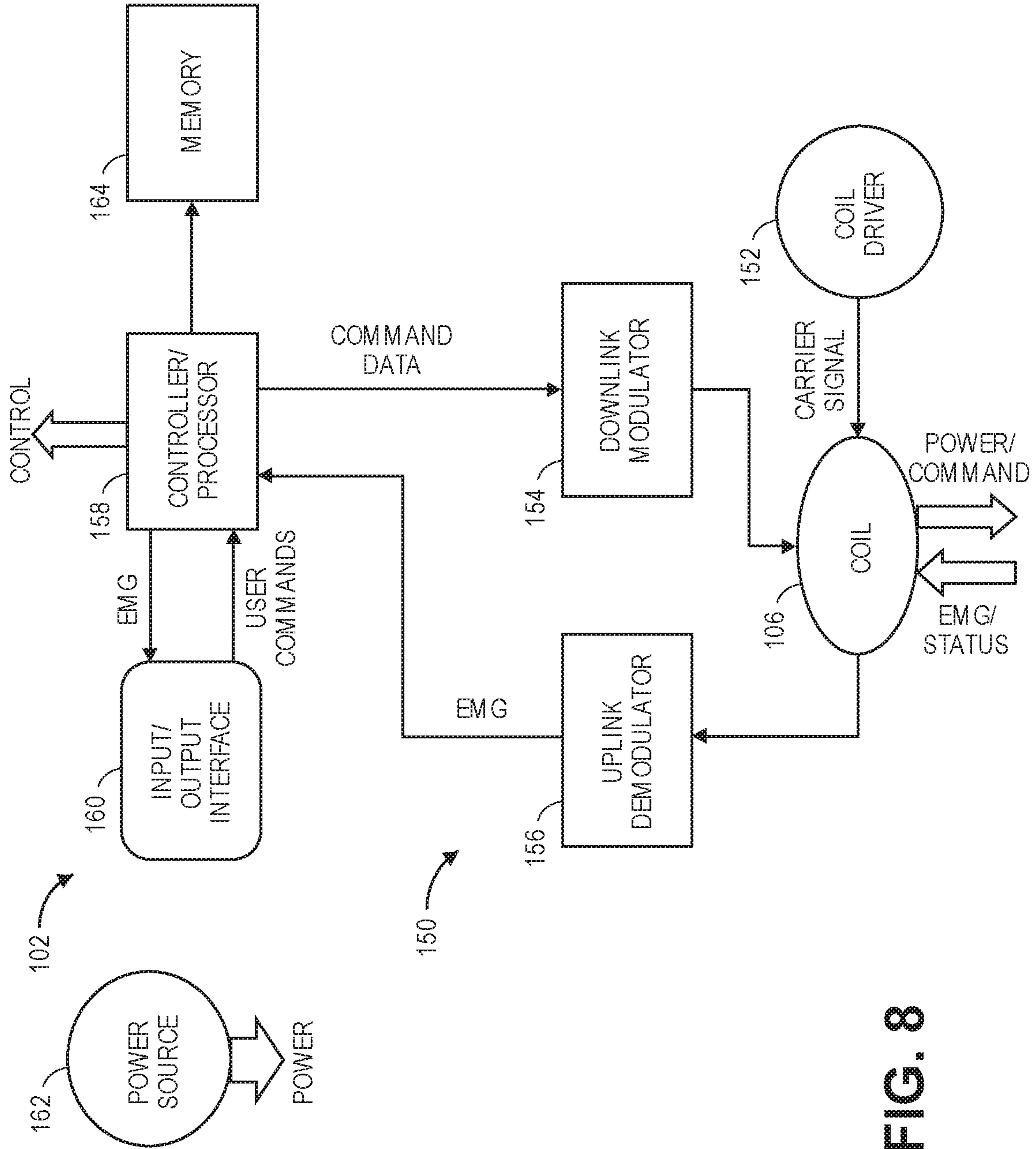


FIG. 8

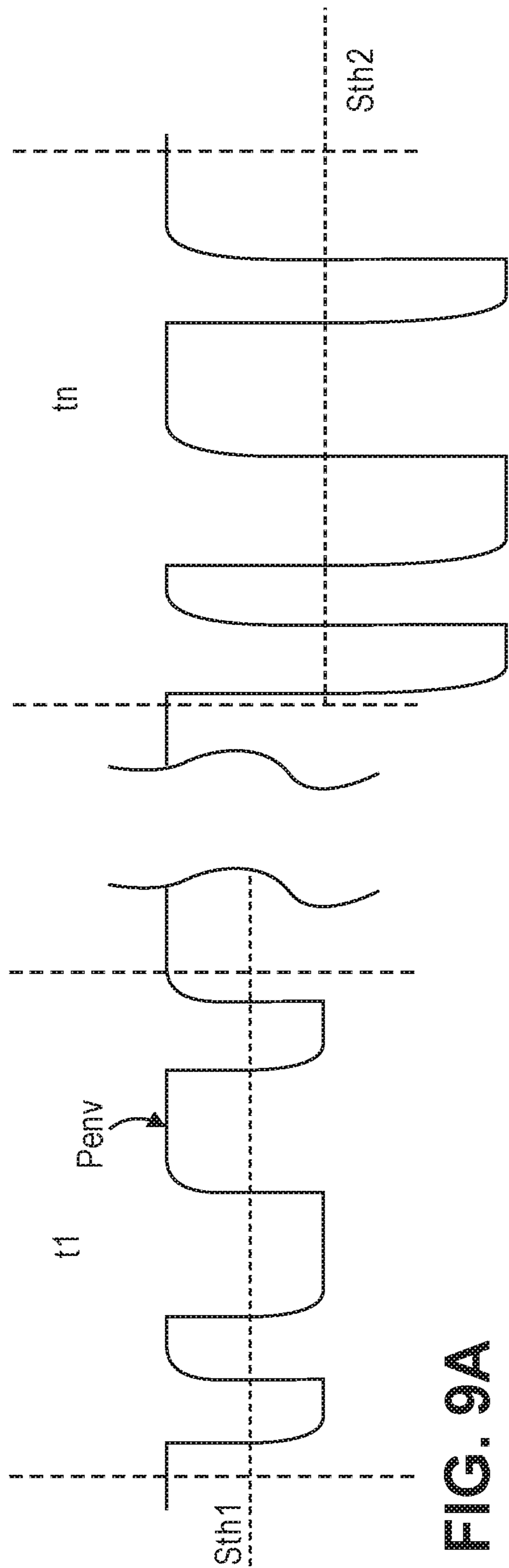


FIG. 9A
(PRIOR ART)

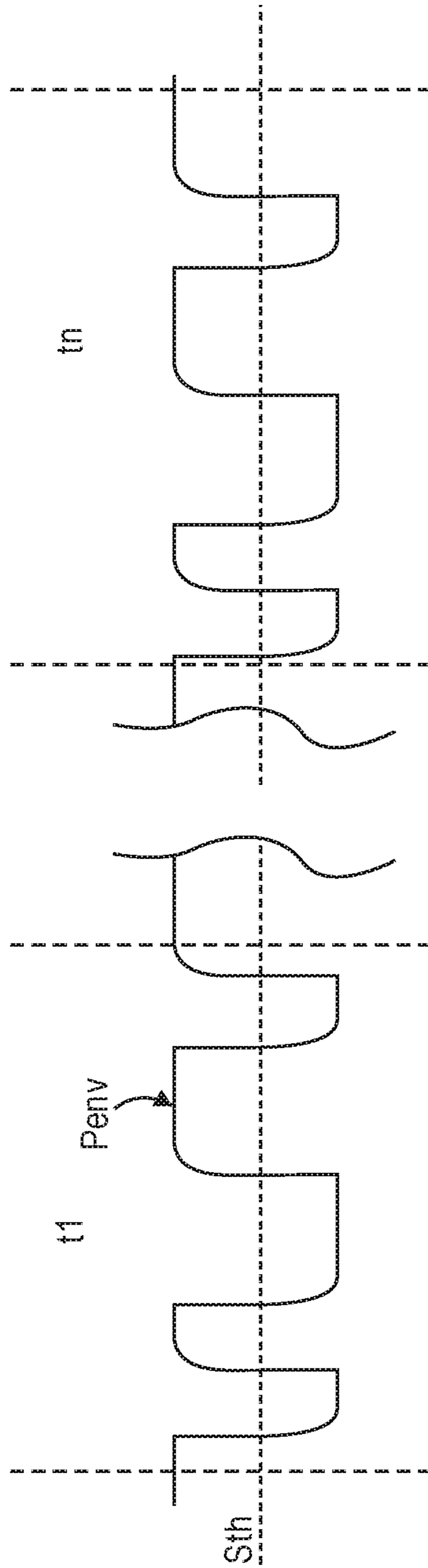


FIG. 9B

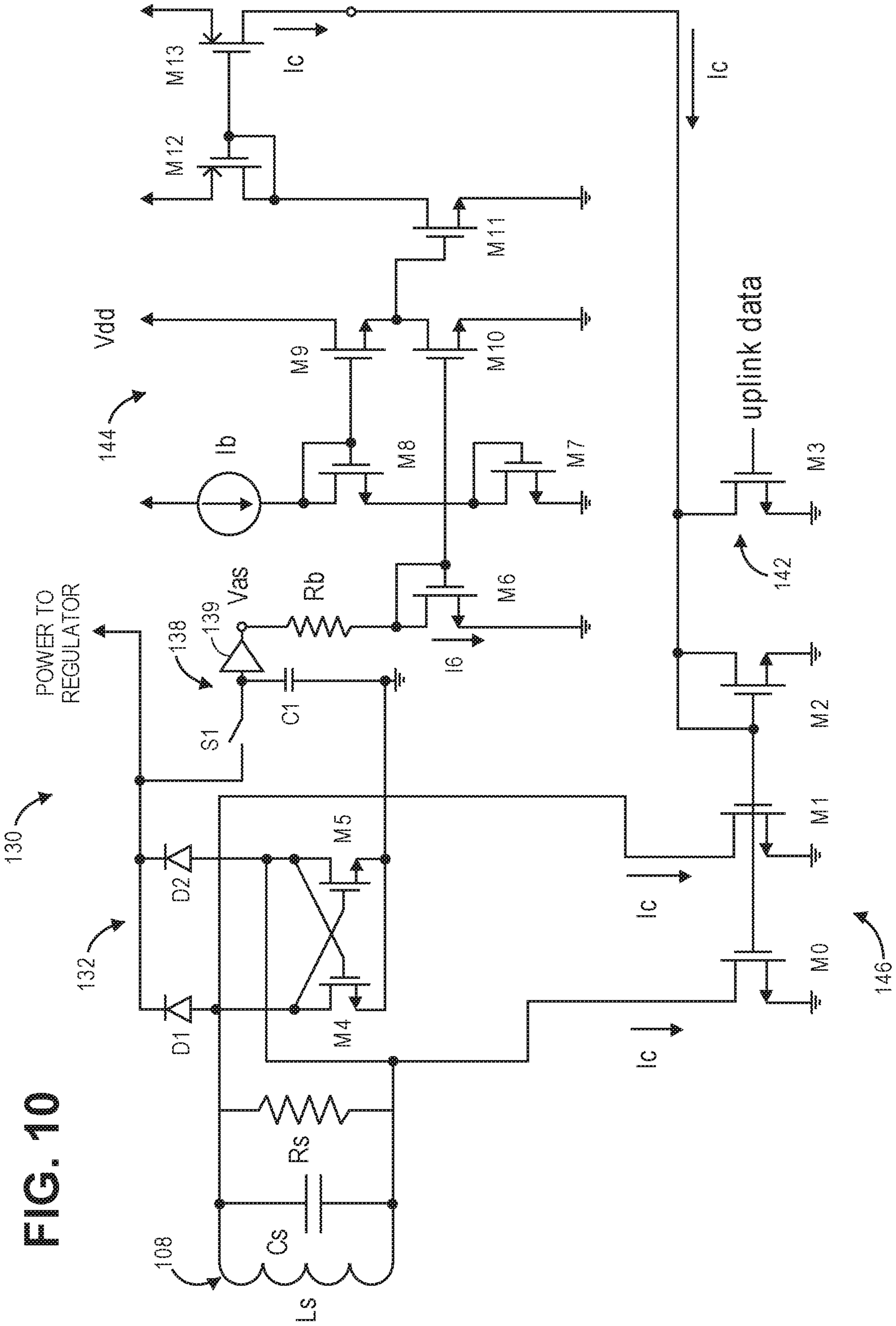


FIG. 10

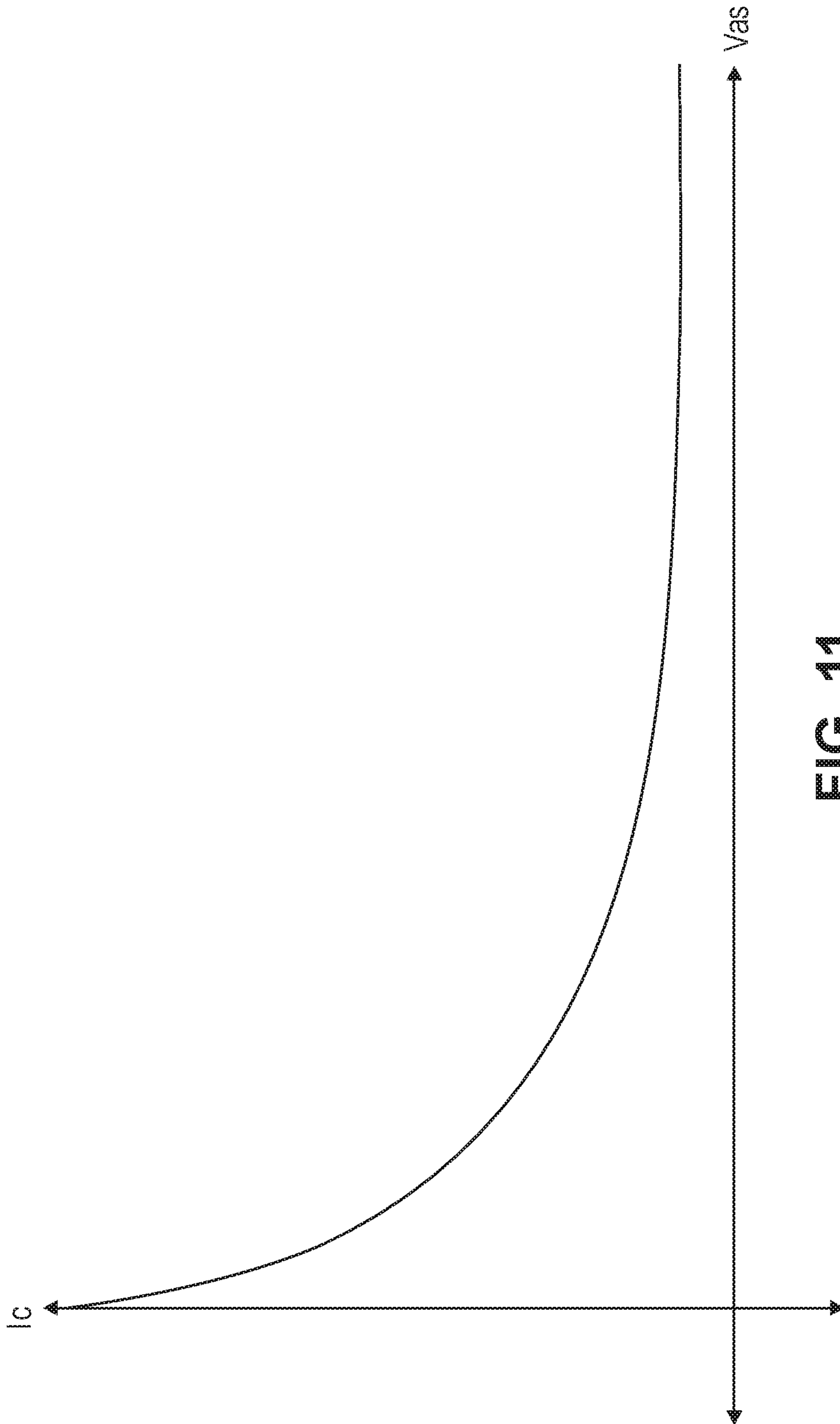


FIG. 11

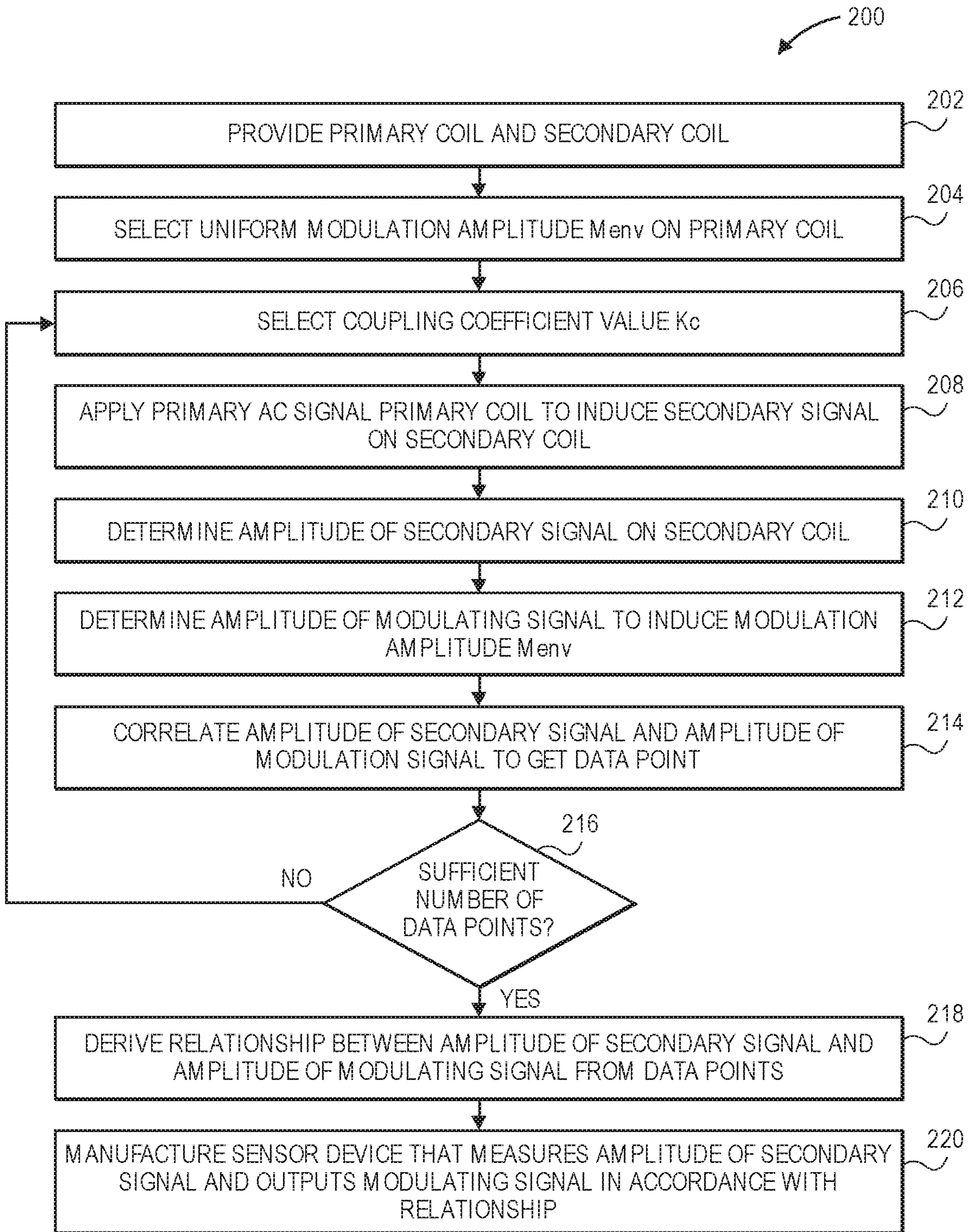


FIG. 12

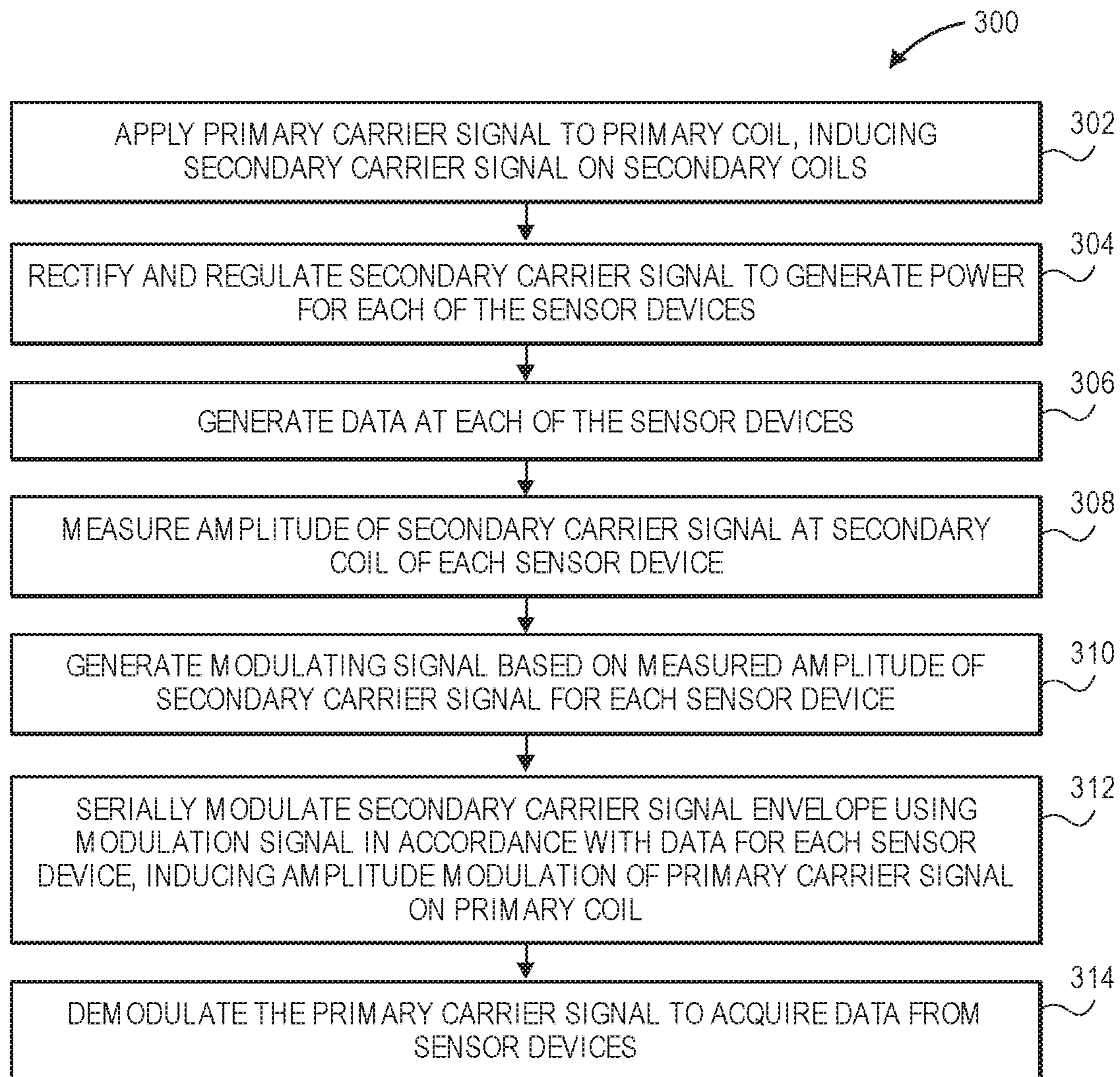


FIG. 13

**MULTIPLE IMPLANT COMMUNICATIONS
WITH ADJUSTABLE LOAD MODULATION
BASED ON RECEIVED SIGNAL
AMPLITUDES**

RELATED APPLICATION

This application is a continuation of U.S. patent application Ser. No. 15/890,509, filed Feb. 7, 2018, which claims the benefit of U.S. Provisional Patent Application 62/456,576, filed Feb. 8, 2017, which is expressly incorporated herein by reference.

FIELD OF THE INVENTION

The present invention generally relates to wireless power/data transfer techniques in medical systems, and specifically relates to such techniques for use in wirelessly providing power to and receiving uplink data from multiple implantable devices.

BACKGROUND OF THE INVENTION

In the field of wireless power and data transfer, inductive coupling has been used to provide power to and communicate with a device without making electrical contact. This technique has been used, for example, with medical systems comprising multiple medical devices that can be implanted inside of the body of a patient. Medical systems utilizing this technique have an external control unit, such as a telemetry controller (TC), and one or more medical devices implanted within the body of a patient. Power transfer and data communication between the external control unit and implanted medical device(s) are provided via an inductive link.

For example, as illustrated in FIG. 1, a conventional power/data transfer system 10 typically includes an external TC 12 capable of performing a medical function (which could be diagnostic and/or therapeutic) and a plurality of implantable medical devices (“implants”) 14, (only two implants 14(y), 14(z) are shown for purposes of brevity in illustration), each of which is capable of sensing physiological signals in the body of a patient and transmitting representative data to the TC 12 in furtherance of performing the medical function.

A primary coil Lp located inside the TC 12 inductively couples and powers secondary coils Ls(y), Ls(z) respectively inside the implanted medical devices 14(y), 14(z). Power is delivered to the implanted medical devices 14 by applying an alternating current (AC) current on the primary coil Lp at a selected transmission frequency Ft. Capacitors Cs(y), Cs(z) are respectively coupled in parallel to the secondary coils Ls(y), Ls(z) to form LC tank circuits that are tuned to resonate at the transmission frequency Ft. In addition to providing power to the medical devices, the coils Lp’s and Ls’s are also utilized for communication between the TC 12 and the implanted medical devices 14. For downlink data from the TC 12 to the implanted medical devices 14, different modulation techniques can be applied to the AC current on the primary coil Lp.

For uplink data from the implanted medical devices 14 to the TC 12, a load modulation technique can be used. In this technique, each implanted medical device 14 transmits uplink data to the TC 12 in a given time slot in a time-division multiplexed manner by modulating a load resistance Rs to a modified load resistance Rs+ΔRs according to the uplink data, where ΔR_L is the amount of change on the

load resistance. Due to the inductive coupling between the primary coil Lp and the corresponding secondary coil Ls, a voltage amplitude change on the primary coil Lp according to the uplink data is obtained. Based on the amplitude change, the TC 12 can demodulate the data sent from a particular implanted medical device 14 at the corresponding time slot utilizing any one or more of a variety of demodulation techniques, including amplitude shift keying (ASK), phase shift keying (PSK), frequency shift keying (FSK), etc.

The amplitudes of the signals received by the TC 12 from the implanted medical devices 14 may differ from each other. For example, depending on the distances, as well as the characteristic of the material, between the primary coil Lp and the secondary coils Ls(y), Ls(z), the coupling coefficients Kc(y), Kc(z) between the primary coil Lp and the respective secondary coils Ls(y), Ls(z) can be different for the different implanted medical devices 14(y), 14(z). The difference in the respective coupling coefficients Kc(y), Kc(z) between the primary coil Lp and the secondary coils Ls(y), Ls(z) will affect the voltage amplitudes on different secondary coils Ls(y), Ls(z). Furthermore, if each medical device 14 utilizes the same amount of load resistance change ΔRs for load modulating the uplink data, the voltage amplitude induced on the primary coil Lp for each implanted medical device 14 will also be different. These voltage amplitude differences on the primary coil Lp due to different coupling coefficients Kc(y), Kc(z) will complicate the circuitry inside the TC 12 that demodulates the uplink data from the induced voltage on the primary coil Lp. Thus, the received signal amplitudes corresponding to the respective implanted medical devices 14(y), 14(z) may be primarily affected by the coupling coefficients Kc(y), Kc(z). The received signal amplitudes corresponding to the respective implanted medical devices 14(y), 14(z) may also be secondarily affected by the different tuning tolerances between the primary coil Lp and the respective secondary coils Ls(y), Ls(z).

For example, referring to FIG. 2, the changes in the amplitude of AC voltage induced on the primary coil Lp due to load modulations at the secondary coils Ls are represented as changes in an envelope signal Senv. A simple demodulator design utilizes an envelope detector to extract the envelope signal Senv from the amplitude changes induced on the primary coil Lp, and a comparator to compare the envelope signal Senv with an appropriate threshold level Sth to determine the uplink data. In the embodiment illustrated in FIG. 2, an ASK modulation technique is employed to encode the envelope signal Senv with data that can then be demodulated to acquire the data therefrom.

For example, as shown in FIG. 3a, an ASK modulated envelope signal Senv1, which contains one of two bits of information (“1” or “0”) during each symbol period (indicated between the dashed lines), can be converted into a digital signal by comparing the envelope signal Senv1 to a threshold level Sth. The data value can be read as switching between “0” and “1” if and when the envelope signal Senv1 crosses the threshold level Sth in the respective symbol period, i.e., from “0” to “1” when the envelope signal Senv1 rises above the threshold level Sth, and from “1” to “0” when the envelope signal Senv1 falls below the threshold level Sth.

In an alternative embodiment shown in FIG. 3b, a four-phase (0°, 90°, 180°, and 270°) PSK modulated envelope signal Senv2, which contains two bits of information (“00,” “01,” “10,” and “11”) during each symbol period (indicated between the dashed lines), can be converted into a digital signal by comparing the envelope signal Senv2 to a thresh-

old level S_{th} . The data value can be read as being “00,” “01,” “10,” and “11,” depending on when and in what direction the envelope signal S_{env2} crosses the threshold level S_{th} in the respective symbol period.

In still another alternative embodiment shown in FIG. 3c, an FSK modulated envelope signal S_{env3} , which contains one of two bits of information (“1” or “0”) during each symbol period (indicated between the dashed lines), can be converted into a digital signal by comparing the envelope signal S_{env3} to a threshold level S_{th} . The data value can be read as “0” and “1,” depending on how many times the envelope signal S_{env3} crosses the threshold level S_{th} in the respective symbol period, i.e., a “0” if the envelope signal S_{env} crosses the threshold level S_{th} three or less times (resulting from the relatively low-frequency portion of the envelope signal S_{env}), a “1” if the envelope signal S_{env} cross the threshold level S_{th} more than three times (resulting from the relatively high-frequency portion of the envelope signal S_{env3})

Regardless of the type of demodulation technique, when the coupling coefficients K_c between the primary coil L_p and the secondary coils $L_s(y)$, $L_s(z)$ of the implanted medical devices $14(y)$, $14(z)$ differ, the peak-to-peak amplitudes of the envelope signals S_{env} on the primary coil L_p for the implanted medical devices $14(y)$, $14(z)$ will be different. In this case, the peak-to-peak amplitude of the envelope signal S_{env} for the implanted medical device $14(y)$ with a relatively high coupling coefficient $K_c(y)$ will be greater than the peak-to-peak amplitude of the envelope signal S_{env} for the implanted medical device $14(z)$ with a relatively low coupling coefficient $K_c(z)$. Thus, different threshold level values $S_{t(y)}$, $S_{t(z)}$ are respectively required to correctly demodulate the uplink data for the implanted medical devices $14(y)$, $14(z)$.

Because a single threshold level value S_t cannot be used to demodulate the uplink data from the different implanted medical devices **14**, a more complicated demodulator design utilizing equalization techniques for the envelope signals S_{env} is required. If the coupling coefficients K_c drift in time, an even more complicated demodulator design using adaptive equalization will become necessary. Alternatively, AC coupling can be used between the envelope detector and the comparator, such that the average value of the envelope signal S_{env} for the uplink data sent by the different implanted medical devices **14** will move to ground, and thus, the threshold level S_t can be set to ground. The uplink data can therefore be correctly demodulated from the envelope signal S_{env} . However, because it will take some time to have the average value of the envelope signal S_{env} to move to ground at the output of the AC coupling whenever a different implanted medical device sends out uplink data, the data within the time required for settling the average value of the envelope signal S_{env} to ground cannot be reliably detected without significantly reducing the uplink data transmission rate.

There, thus, remains a need for providing a simpler means that allows demodulation of uplink data sent from multiple implantable medical devices without having to reduce the uplink data transmission rate.

SUMMARY OF THE INVENTION

In accordance with a first aspect of the present inventions, a medical system comprises a telemetry controller (e.g., an external telemetry controller) a primary coil, a coil driver configured for applying a primary carrier signal having an envelope capable of being modulated to the primary coil,

and a demodulator configured for amplitude demodulating the modulated primary carrier signal envelope to acquire data. In one embodiment, the demodulator is configured for amplitude demodulating the modulated primary carrier signal envelope by detecting the modulated primary carrier signal envelope, and comparing the detected envelope of the primary carrier signal to a threshold level. In this case, the amplitude of the threshold level may be between a minimum and a maximum of the modulated primary carrier signal envelope, e.g., centered between the minimum and the maximum of the modulated primary carrier signal envelope.

The medical system further comprises a plurality of implantable medical devices, each of which comprises a secondary coil on which a secondary carrier signal having an envelope may be induced in response to the application of the primary carrier signal on the primary coil, an amplitude detector configured for measuring an amplitude of the secondary carrier signal, and a modulator configured for amplitude modulating the secondary carrier signal envelope in accordance with data, thereby inducing an amplitude modulation of the primary carrier signal envelope on the primary coil. In one embodiment, the data is physiological data of the patient, in which case, each of the implantable medical devices may further comprise at least one sensor configured for acquiring the physiological data from the patient. In other embodiments, the data may be operational status data of each of the implantable medical devices.

The modulators of the implantable medical devices are configured for modulating the secondary carrier signal envelopes (e.g., via load modulation) based on the measured amplitudes (e.g., peak amplitudes) of the respective secondary carrier signals, such that a variation of the amplitude modulation of the primary carrier signal envelope between the implanted medical devices is decreased to compensate for different coupling coefficients between the primary coil and the secondary coils. In one embodiment, the amplitude detector of each of the implantable medical devices is configured for measuring the amplitude of the secondary carrier signal on the respective secondary coil by measuring a voltage across the respective secondary coil, and the modulator of each of the implantable medical devices is configured for amplitude modulating the envelope of the secondary carrier signals by modifying a load current associated with the secondary coil as a function of the measured voltage.

In another embodiment, the primary carrier signal envelope is substantially uniformly amplitude modulated for the implanted medical devices. For example, a variation in modulation amplitude of the primary carrier signal envelope between the implanted medical devices may be less than 50%, and preferably, less than 20%. In still another embodiment, the modulators are configured for modulating the envelopes of the secondary carrier signals, such that modulation magnitudes of the modulated envelopes of the secondary carrier signals vary in an inversely varying relationship with the coupling coefficients between the respective secondary coils and the primary coil. In an optional embodiment, each of the implantable medical devices further comprises a rectifier configured for rectifying and regulating the secondary carrier signal for powering circuitry within the respective implantable medical device.

In accordance with a second aspect of the present inventions, a method of communicating between a telemetry controller (which may be external) and a plurality of medical devices implanted within a patient is provided. The telemetry controller has a primary coil and each of the medical

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devices has a secondary coil, and coupling coefficients between the primary coil and the secondary coils differ from each other.

The method comprises applying a primary carrier signal having an envelope to the primary coil, thereby respectively inducing a secondary carrier signal having an envelope on each of the secondary coils, generating data by each of the implanted medical devices, and measuring an amplitude of the secondary carrier signal on each of the secondary coils. In one method, the generated data may be physiological data acquired from the patient by each of the implantable medical devices. In other methods, the generated data may be operational status data of each of the implantable medical devices.

The method further comprises sequentially amplitude modulating each of the secondary carrier signal envelopes in accordance with the data generated by the respective implanted medical device, thereby inducing an amplitude modulation of the primary carrier signal envelope on the primary coil for the implanted medical devices. In one method, the primary carrier signal envelope is substantially uniformly amplitude modulated for the implanted medical devices. For example, a variation in modulation amplitude of the primary carrier signal envelope between the implanted medical devices may be less than 50%, and preferably, less than 20%.

The secondary carrier signal envelopes are modulated (e.g., via load modulation) based on the measured amplitudes (e.g., peak amplitudes) of the respective secondary carrier signals, such that a variation of the amplitude modulation of the primary carrier signal envelope between the implanted medical devices is decreased to compensate for the different coupling coefficients. In one method, each of the secondary carrier signal envelopes is modulated, such that modulation magnitudes of the modulated envelopes of the secondary carrier signals vary in an inversely varying relationship with the coupling coefficients between the respective secondary coils and the primary coil. In another method, measuring the amplitude of the secondary carrier signal on each of the secondary coils comprises measuring a voltage across the respective secondary coil, and amplitude modulating the envelope of each of the secondary carrier signals comprises modifying a load current associated with the secondary coil as a function of the measured voltage.

The method further comprises amplitude demodulating the modulated primary carrier signal envelope to acquire the data from the implanted medical devices. In one method, amplitude demodulating the modulated primary carrier signal envelope comprises detecting the modulated primary carrier signal envelope, and comparing the detected envelope of the primary carrier signal to a threshold level. In this case, the amplitude of the threshold level may be between a minimum and a maximum of the modulated primary carrier signal envelope, e.g., centered between the minimum and the maximum of the modulated primary carrier signal envelope. An optional method comprises generating power for each of the implanted medical devices from the respective secondary carrier signal.

In accordance with a third aspect of the present inventions, an implantable medical device for communicating with a telemetry controller having a primary coil on which a primary carrier signal is applied is provided. The implantable medical device comprises a secondary coil on which a secondary carrier signal having an envelope may be induced in response to the application of the primary carrier signal on the primary coil. The implantable medical device further comprises an amplitude detector configured for measuring

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an amplitude (e.g., peak amplitude) of the secondary carrier signal, processing circuitry configured for selecting a magnitude of a modulation of the secondary carrier signal in accordance with an inversely varying relationship with the measured amplitude of the secondary carrier signal, and a modulator configured for applying the selected modulation magnitude to the secondary carrier signal envelope (e.g., via load modulation) in accordance with data, thereby inducing an amplitude modulation of the primary carrier signal envelope on the primary coil. In one embodiment, the data is physiological data of the patient, in which case, the implantable medical devices may further comprise at least one sensor configured for acquiring the physiological data from the patient. In other embodiments, the data may be operational status data of the implantable medical devices.

In one embodiment, the amplitude detector is configured for measuring the amplitude of the secondary carrier signal by measuring a voltage across the secondary coil, and the modulator is configured for amplitude modulating the envelope of the secondary carrier signal by modifying a load current associated with the secondary coil. In an optional embodiment, the implantable medical device further comprises a rectifier configured for rectifying and regulating the secondary carrier signal for powering circuitry within the implantable medical device. The implantable medical device may comprise a biocompatible casing containing the secondary coil, amplitude detector, processing circuitry, and modulator.

In accordance with a fourth aspect of the present invention, a method of communicating between a telemetry controller (which may be external) and a medical device implanted within a patient is provided. The telemetry controller has a primary coil, and the medical device has a secondary coil. The method comprises generating data by the implanted medical device, and applying a primary carrier signal having an envelope to the primary coil, thereby respectively inducing a secondary carrier signal having an envelope on the secondary coil. In one method, the generated data may be physiological data acquired from the patient by the implantable medical device. In other methods, the generated data may be operational status data of the implantable medical device.

The method further comprises measuring an amplitude (e.g., a peak amplitude) of the secondary carrier signal on the secondary coils, selecting a magnitude of a modulation of the secondary carrier signal in accordance with an inversely varying relationship with the measured amplitude of the secondary carrier signal, and applying the selected modulation magnitude to the secondary carrier signal envelope (e.g., via load modulation) in accordance with the physiological data acquired by the implanted medical device, such that the primary carrier signal envelope is amplitude modulated. In one method, measuring the amplitude of the secondary carrier signal on the secondary coil may comprise measuring a voltage across the secondary coil, and wherein amplitude modulating the envelope of the secondary carrier signal comprises modifying a load current associated with the secondary coil.

The method further comprises amplitude demodulating the modulated primary carrier signal envelope to acquire the physiological data from the implanted medical device. In one method, amplitude demodulating the modulated primary carrier signal envelope may comprise detecting the modulated primary carrier signal envelope, and comparing the detected envelope of the primary carrier signal to a threshold level. In this case, the amplitude of the threshold level may

be centered between a minimum and a maximum of the modulated primary carrier signal envelope.

In accordance with a fifth aspect of the present inventions, a method of manufacturing an implantable medical device is provided. The method comprises (a) selecting a uniform value for an amplitude modulation induced on a primary signal envelope, and (b) selecting a coupling coefficient value between a primary coil and secondary coil. The method further comprises (c) applying a fixed alternating current (AC) signal to the primary coil, thereby respectively inducing a secondary signal on the secondary coil for the selected coupling coefficient value, (d) determining an amplitude of the secondary signal (e.g., a peak amplitude) for the coupling coefficient value, and (e) determining an amplitude of a modulating signal for modulating an envelope of the secondary signal in a manner that induces an amplitude modulation on the primary coil that is substantially equal to the selected uniform amplitude modulation value, e.g., by adjusting the modulating signal until the amplitude modulation induced on the primary signal envelope is substantially equal to the selected uniform amplitude modulation value. In one method, determining the amplitude of the secondary carrier signal on the secondary coil comprises determining a voltage across the secondary coil, in which case, the modulating signal may define a change in a current in the secondary coil. Steps (c)-(e) may, e.g., be simulated or actually performed.

The method further comprises (f) correlating the determined amplitude of the secondary signal and the determined amplitude of the modulating signal to create a data point, and (g) repeating steps (b)-(f) for different coupling coefficient values to create a plurality of data points. The method further comprises (h) deriving a relationship between the respective amplitudes of the secondary signal and the modulating signal from the plurality of data points, and (i) manufacturing the implantable medical device having the secondary coil and processing circuitry configured for outputting a modulating signal in response to an input of a measured amplitude of a secondary carrier signal induced on the secondary coil in accordance with the derived relationship, such that an envelope of the secondary carrier signal is modulated.

Other and further aspects and features of the invention will be evident from reading the following detailed description of the preferred embodiments, which are intended to illustrate, not limit, the invention.

BRIEF DESCRIPTION OF THE DRAWINGS

The drawings illustrate the design and utility of preferred embodiments of the present invention, in which similar elements are referred to by common reference numerals. In order to better appreciate how the above-recited and other advantages and objects of the present inventions are obtained, a more particular description of the present inventions briefly described above will be rendered by reference to specific embodiments thereof, which are illustrated in the accompanying drawings. Understanding that these drawings depict only typical embodiments of the invention and are not therefore to be considered limiting of its scope, the invention will be described and explained with additional specificity and detail through the use of the accompanying drawings in which:

FIG. 1 is a block diagram of a prior art power/data transfer system for powering and communicating with implantable medical devices via a telemetry controller;

FIG. 2 is a diagram of a primary carrier signal on a primary coil of the telemetry controller that has been modulated in accordance with an amplitude shift keying (ASK) technique with uplink data received from the medical devices of FIG. 1;

FIG. 3a is a diagram of an envelope signal detected from the modulated primary carrier signal of FIG. 2;

FIG. 3b is a diagram of an envelope signal alternatively detected from a primary carrier signal that has been modulated in accordance with a phase shift keying (PSK) technique with uplink data received from the medical devices of FIG. 1;

FIG. 3c is a diagram of an envelope signal alternatively detected from a primary carrier signal that has been modulated in accordance with a frequency shift keying (FSK) technique with uplink data received from the medical devices of FIG. 1;

FIG. 4 is a pictorial of a prosthetic control system constructed in accordance with one embodiment of the present inventions;

FIG. 5a is a block diagram of a telemetry controller and a plurality of sensor devices for use in the prosthetic control system of FIG. 4, particularly showing the induction of different secondary carrier signals on the secondary coils of the sensor devices in response to the application of a primary carrier signal on the primary coil of the telemetry controller;

FIG. 5b is a block diagram of the telemetry controller and sensor devices of FIG. 5a, particularly showing the induction of amplitude modulations on the primary carrier signal on the primary coil of the telemetry coil in response to the application of amplitude modulations on the secondary coils of the respective sensor devices;

FIG. 6 is a block diagram of one of the sensor devices illustrated in FIGS. 5a and 5b;

FIG. 7a is a schematic illustrating one embodiment of processing circuitry used to generate a modulation current for load modulating the secondary carrier signal on the secondary coil of the sensor device of FIG. 6 by varying the loading current on the secondary coil L_s ;

FIG. 7b is a schematic illustrating another embodiment of processing circuitry used to generate a modulation current for load modulating the secondary carrier signal on the secondary coil of the sensor device of FIG. 6 by varying the loading resistance on the secondary coil L_s ;

FIG. 7c is a schematic illustrating still another embodiment of processing circuitry used to generate a modulation current for load modulating the secondary carrier signal on the secondary coil of the sensor device of FIG. 6 by varying the equivalent capacitance of the capacitor C_s ;

FIG. 8 is a block diagram of the telemetry controller illustrated in FIGS. 5a and 5b;

FIG. 9a is a diagram of a primary carrier signal on a primary coil of a prior art telemetry controller, particularly showing a non-uniform modulation of the primary carrier signal induced by the modulation of secondary carrier signals on the secondary coils of sensor devices;

FIG. 9b is a diagram of a primary carrier signal on the primary coil of the telemetry controller of FIG. 8, particularly showing a uniform modulation of the primary carrier signal induced by the modulation of secondary carrier signals on the secondary coils of the sensor devices of FIGS. 5a and 5b;

FIG. 10 is a schematic of telemetry/power circuitry of the sensor device of FIG. 6;

FIG. 11 is an exemplary function between the voltage amplitude of a secondary carrier signal and the amplitude of a modulating current generated by the telemetry/power circuitry of FIG. 10;

FIG. 12 is a flow diagram illustrating one method of manufacturing the sensor device of FIGS. 5a and 5b; and

FIG. 13 is a flow diagram illustrating one method of communicating uplink data from the sensor devices to the telemetry controller of FIGS. 5a and 5b in a manner that equalizes the amplitude modulation on the primary carrier signal of the primary coil.

DETAILED DESCRIPTION OF THE EMBODIMENTS

Referring to FIG. 4, a medical system 100 constructed in accordance with one embodiment of the present inventions will now be described. The medical system 100 generally comprises an external telemetry controller (TC) 102 and a plurality of implantable medical devices 104. In the illustrated embodiment, the medical system 100 takes the form of a prosthetic control system.

In this case, the implantable medical devices 104 may take the form of sensor devices that are implanted within a residual portion of an amputated limb 52 of a patient 50 respectively adjacent muscles of interest for detecting muscle contraction, for example, by monitoring electromyogram (EMG) signals of the muscles of interest. The prosthetic control system 100 comprises a bionic prosthesis 54 having a prosthetic forearm 56 and prosthetic hand 58. The TC 102 may be incorporated into the bionic prosthesis 54, and is configured for delivering power to and receiving EMG data from the sensor devices 104. To facilitate power transfer and communications, the TC 102 comprises a primary coil 106, which may be incorporated into the socket portion of the bionic prosthesis 54 in a manner that it surrounds the sensor devices 104 implanted within the residual limb portion 52 of the patient 50. The TC 102 comprises power transfer and communication circuitry that inductively powers and communicates with the implanted sensor devices 104 via the primary coil 106.

The prosthetic control system 100 further comprises a prosthetic controller 110 coupled to the TC 102 via a cable 112 for receiving EMG data from TC 102, and is further coupled to motors (not shown) in the bionic prosthesis 54 to control movement of the prosthetic arm 56 and prosthetic hand 58. The prosthetic controller 110 may be worn by the patient 50, e.g., on the waist. The prosthetic control system 100 may further comprises one or more batteries (not shown), which may be physically integrated into the prosthesis 54 or otherwise contained in the prosthetic controller 110, for providing power to the circuitry within the TC 102 and prosthetic controller 110.

Thus, the prosthetic control system 100 allows the patient 50 to control the prosthetic forearm 56 and prosthetic hand 58 by attempting to contract the muscles in the residual limb portion 52. Different muscles or different portions of the muscles would correspond to independently movable parts, such as the elbow, wrist, and fingers of the bionic prosthesis 54. When a sensor device 104 detects contraction in a muscle or portion of a muscle, it communicates the resulting EMG data to the prosthetic controller 110 via the TC 102 that the muscle or portion of a muscle was contracted. The EMG data identifies the muscle that has been contracted, as well as the magnitude of the contraction. The prosthetic controller 110 then controls the bionic prosthesis 54 to move

the independently movable part that corresponds with the muscle that was contracted according to the magnitude of the contraction.

Although the TC 102 and prosthetic controller 110 are shown as being separate physical units in FIG. 4, it should be appreciated that the TC 102 and prosthetic controller 110 may be integrated into a single physical unit that is incorporated into the prosthesis 54 or otherwise worn by the patient 50. It should also be appreciated that although the prosthetic control system 100 has been described as being a prosthetic control system, the prosthetic control system 100 can be any medical system that performs a diagnostic or therapeutic function. Likewise, although the implantable medical devices 102 are described as being EMG sensors, the implantable medical devices 102 may take the form of any medical device that performs a diagnostic or therapeutic function. Furthermore, although the TC 102 is described herein as being external to the patient 50, it should be appreciated that the TC 102 may take the form of, or otherwise be incorporated into, an implantable device that communicates with the other sensor devices 104.

In a conventional manner, the TC 102 may apply an exemplary unmodulated primary alternating current (AC) carrier signal P_{car} to the primary coil 106, which induces exemplary unmodulated secondary AC carrier signals $Scar_1$ - $Scar_n$ on secondary coils 108 (shown in FIGS. 5a and 5b) of respective sensor devices 104(1)-104(n). The sensor devices 104(1)-104(n) may serially (one at a time) amplitude modulate the envelopes $Senv_1$ - $Senv_n$ of the secondary carrier signals $Scar$ on the respective secondary coils 108 in accordance with data for transmission to the TC 102, thereby inducing an amplitude modulation of the envelope $Penv$ of the primary carrier signal P_{car} on the primary coil 106 that can be demodulated to acquire the data from the sensor devices 104. It should be appreciated that, for the purposes of this specification, "amplitude modulation" refers to any modulation where the peak-to-peak amplitude of a carrier signal is modified, and includes, e.g., such modulation techniques as AM, ASK, FSK, PSK, etc. In the specific embodiment illustrated herein, the sensor devices 104(1)-104(n) amplitude modulate secondary carrier signals on respective secondary coils using load modulation.

As discussed in the background, if the coupling coefficients Kc_1 - Kc_n between the primary coil 106 and respective secondary coils 108 differ from each other, without compensation, the same load modulations applied to the secondary carrier signal envelopes $Senv$ will induce different amplitude modulations on the primary carrier signal envelope $Penv$ (i.e., the peak-to-peak amplitude of the primary carrier signal envelope $Penv$ will be different for the sensor devices 104), which may require more complicated demodulation circuitry and/or slower data transmission rate to accurately acquire the data from the primary carrier signal P_{car} .

Significantly, the prosthetic control system 100 is capable of equalizing the magnitude of the modulation of the primary carrier signal envelope $Penv$ on the primary coil 106 of the TC 102 amongst the sensor devices 104 by load the secondary carrier signal envelopes $Senv$ on the secondary coils 108, such that modulation magnitudes of the modulated secondary carrier signal envelopes $Senv$ vary in an inversely varying relationship to the coupling coefficients Kc_1 - Kc_n between the respective secondary coils 104(1)-104(n) and the primary coil 102. In other words, as a coupling coefficient Kc between the primary coil 106 and a particular secondary coil 108 increases, the modulation magnitude of the modulated secondary carrier signal envelope $Senv$ on the

secondary coil **108** is decreased, and conversely, as a coupling coefficient K_c between the primary coil **106** and a particular secondary coil **108** decreases, the modulation magnitude of the modulated secondary carrier signal envelope S_{env} on the secondary coil **108** is increased.

In order to select the proper modulation magnitudes for the secondary carrier signal envelopes S_{env} on the secondary coils **108**, the prosthetic control system **100** indirectly measures the different coupling coefficients K_{c1} - K_{cn} between the primary coil **106** and the secondary coils **108** by measuring the amplitudes of the unmodulated secondary carrier signals across the respective secondary coils **108**. That is, it is known that the amplitude of a secondary carrier signal induced on a secondary coil in response to the application of a primary carrier signal on a primary coil is proportional to the coupling coefficient between the primary coil and the secondary coil.

For example, as shown in FIG. **5a**, the peak-to-peak amplitudes of the respective secondary carrier signals on the secondary coils **108** will vary in accordance with the coupling coefficients K_{c1} - K_{cn} . That is, if the coupling coefficient K_{c1} between the primary coil **106** and the secondary coil **108(1)** is relatively high, the amplitude of the unmodulated secondary carrier signal on the secondary coil **108(1)** will be relatively high; if the coupling coefficient K_{c2} between the primary coil **106** and the secondary coil **108(2)** is relatively medial, the amplitude of the unmodulated secondary carrier signal on the secondary coil **108(2)** will be relatively medial; and if the coupling coefficient K_{cn} between the primary coil **106** and the secondary coil **108(n)** is relatively low, the amplitude of the unmodulated secondary carrier signal on the secondary coil **108(n)** will be relatively low.

Thus, the amplitude of the secondary carrier signal (preferably, unmodulated) on a secondary coil provides an accurate indication of the coupling coefficient between the primary coil and the secondary coil, and thus, can be used to select the modulation magnitude for the secondary carrier signal envelope S_{env} on that secondary coil. Thus, the modulation magnitude of the secondary carrier signal envelope S_{env} on any given secondary coil **108** will inversely vary with the measured amplitude of the unmodulated secondary carrier signal.

As shown in FIG. **5b**, if the coupling coefficient K_{c1} between the primary coil **106** and the secondary coil **108(1)** is relatively high, the secondary carrier signal envelope S_{env} on the secondary coil **108(1)** will be load modulated such that it has a relatively low modulation magnitude; if the coupling coefficient K_{c2} between the primary coil **106** and the secondary coil **108(2)** is relatively medial, the secondary carrier signal envelope S_{env} on the secondary coil **108(2)** will be load modulated such that it has a relatively medial modulation magnitude; and if the coupling coefficient K_{cn} between the primary coil **106** and the secondary coil **108(2)** is relatively low, the secondary carrier signal envelope S_{env} on the secondary coil **108(n)** will be load modulated such that it has a relatively high modulation magnitude.

In this manner, variation of the modulation magnitude of the modulated primary carrier signal envelope P_{env} on the primary coil **106** between the sensor devices **104** will be decreased to compensate for the different coupling coefficients K_{c1} - K_{cn} (and secondarily, to compensate for any variation in tuning tolerances) between the primary coil **106** and the secondary coils **108**. Preferably, the primary carrier signal envelope P_{env} is substantially uniformly amplitude modulated for the implanted sensor devices **104**. For example, a variation in the modulation amplitude of the

primary carrier signal envelope P_{env} between the implanted sensor devices **104** is less than 50%, and preferably less than 20%.

Referring now to FIG. **6**, each sensor device **104** is capable of sensing EMG signals. To this end, the sensor device **104** comprises two differential recording electrodes **120a**, **120b** configured for sensing electrical activity within the muscle fibers in which the sensor device **104** is implanted and outputting a raw analog EMG signal. In alternative embodiments, the sensor device **104** may sense electrical impedance, field potential, evoked potential from nerves, temperature, pressure, tension, translucence, reflectance, pH, motion, inertial, chemical, respiration, vascular pulsation, heartbeat, ECG, EKG, EEG, EOG, etc.

The sensor device **104** further comprises one or more adjustable gain amplifiers **122** configured for amplifying the EMG signal; a filter **124** configured for obtaining an envelope, integrating, or sampling the EMG signal; an analog-to-digital converter (A/D) converter **126** configured for selectively transforming either the raw EMG signal output from the amplifier(s) **122** or the filtered EMG signal output from the filter **124** into a digitized EMG signal; and control logic **128** (e.g., command processor, frame generator, PLL logic, command decoder, and error correction circuitry) configured for controlling and operating the sensor device **104** in accordance with commands received from the TC **102**. The filter **124** can also be realized digitally. In this case, the filter **124** would be placed after the A/D converter **126**.

The sensor device **104** further comprises telemetry/power circuitry **130** configured for receiving commands and power from the TC **102** and transmitting the EMG signal (either raw or filtered) to the TC **102**. In the illustrated embodiment, the sensor device **104** utilizes a robust half-duplex data link for transmitting the filtered or raw EMG signal to the TC **102** and receiving command data from the TC **102**.

To this end, the telemetry/power circuitry **130** comprises the aforementioned secondary coil **108** on which the secondary carrier signal is induced in response to the application of the primary carrier signal on the primary coil **106** of the TC **102**. The telemetry/power circuitry **130** utilizes secondary carrier signal as both a source of power and as a downlink/uplink carrier signal. The telemetry/power circuitry **130** further comprises a rectifier **132** and power regulator **134** for rectifying and regulating the inductive carrier signal received at the secondary coil **108** for powering the circuitry of the sensor device **104**. In alternative embodiments, the sensor device **104** may include a rechargeable battery (not shown) for storing the electrical energy, or a non-rechargeable battery, in which case, power may be supplied to the circuitry of the sensor device **104** without connection to the TC **102**. In this case, the sensor device **104** may further comprise memory (not shown) for storing the EMG data that can be subsequently transmitted via a dedicated communication coil upon interrogation of the sensor device **104** by the TC **102**.

The telemetry/power circuitry **130** further comprises a downlink inductive demodulator **136** configured for demodulating command data received from the TC **102** from the secondary carrier signal at the secondary coil **108**. In the illustrated embodiment, the downlink inductive demodulator **136** is an amplitude modulation (AM) demodulator that demodulates the downlink data by measuring the amplitude variations of the secondary carrier signal.

More significant to the present inventions, the telemetry/power circuitry **130** comprises an amplitude detector **138** configured for measuring the amplitude of the secondary carrier signal. In the illustrated embodiment, the amplitude

detector **138** is configured for measuring a peak amplitude of the secondary carrier signal, although in alternative embodiments, the amplitude detector **138** may, e.g., measure a root mean square (RMS) amplitude of the secondary carrier signal. The telemetry/power circuitry **130** further comprises processing circuitry **140** configured for selecting a magnitude of a load modulation of the secondary carrier signal at the secondary coil **108** in accordance with an inversely varying relationship with the measured amplitude of the secondary carrier signal. That is, the greater the measured amplitude of the secondary carrier signal, the less the selected modulation magnitude of the secondary carrier signal, and the less the measured amplitude of the secondary carrier signal, the greater the selected modulation magnitude of the secondary carrier signal.

In the illustrated embodiment, the processing circuitry **140** may, e.g., select the modulation magnitude via a current-controlled variable current source **140a**, as illustrated in FIG. **7a**. The current-controlled variable current source **140a** is controlled via a modulating current I_c , such that a modulation voltage V_m (i.e., a change in the voltage across the secondary coil L_s) is selected. As the current output of the variable current source **140a** increases, the modulation voltage V_m increases. Alternatively, the processing circuitry **140** may, e.g., select the modulation magnitude via a current-controlled variable resistor **140b**, as illustrated in FIG. **7b**. The variable resistor **140b** is controlled via a modulating current I_c , such that the modulation voltage V_m is selected. As the resistance of the variable resistor **140b** decreases, the modulation voltage V_m increases. Alternatively, the processing circuitry **140** may, e.g., select the modulation magnitude via a current-controlled variable capacitor **140c**, as illustrated in FIG. **7c**. The variable capacitor **140c** is controlled via a modulating current I_c , such that the modulation voltage V_m is selected. As the capacitance of the variable capacitor **140c** increases, the modulation voltage V_m increases. Although the processing circuitry **140** utilizes a current input I_c as the control signal to control the variable current source **140a** in FIG. **7a**, the variable resistor **140b** in FIG. **7b**, or the variable capacitor **140c** in FIG. **7c**, it should be appreciated that the processing circuitry **140** may alternatively utilize a control voltage to control the variable current source **140a**, variable resistor **140b**, or variable capacitor **140c**.

Referring back to FIG. **6**, the telemetry/power circuitry **130** further comprises an uplink modulator **142** configured for applying the selected modulation magnitude to the secondary carrier signal at the secondary coil **108** in accordance with the raw or filtered EMG received from the A/D converter **126**, thereby inducing an amplitude modulation of the primary carrier signal envelope on the primary coil **106**. In optional embodiments, operational status data can be transmitted by the sensor device **104** to the external control unit **16** via the secondary coil **108** to provide, for example, battery status information or other operational information of the sensor device **104**, in which case, the uplink modulator **142** may be configured for applying the selected modulation magnitude to the secondary carrier signal at the secondary coil **108** in accordance with the operational status data. In the alternative case wherein the implantable medical device is a therapeutic device, such as a neurostimulator, the operational status data may include electrical measurements made by the neurostimulator while stimulating a neuromuscular pathway.

The sensor device **104** may take the form of a miniaturized cylindrical sensing device, with the circuitry being implemented as a sub-assembly on a single-chip integrated

circuit mounted on a ceramic substrate sandwiched between two halves of a cylindrical magnetic core around which the inductive coil is wound. The electronics are encapsulated in a cylindrical ceramic package that include two metal end-caps at opposite ends of the ceramic package that serve as the differential recording electrodes. Such an implantable sensor device allows the EMG signals to be detected at the implantation site of this device. An example of such an implantable sensor device **104** is the IMES® device manufactured by The Alfred Mann Foundation for Scientific Research and described in *Implantable Myoelectric Sensors (IMESs) for Intramuscular Electromyogram Recording*, IEEE Trans Biomed Eng., 2009, January, pp. 159-171. In an alternative embodiment, the sensor device **104** may include a lead (not shown) on which the electrodes are carried, so that EMG signals can be detected at a location remote from the implantation site of the body of the device.

Referring to FIG. **8**, the TC **102** comprises telemetry/power circuitry **150** configured for transmitting commands and power to the sensor devices **104** and receiving the EMG signal (either raw or filtered), or status signals, from the sensor devices **104**. To this end, the telemetry/power circuitry **150** comprises the aforementioned primary coil **106** and a coil driver **152** configured for applying the primary carrier signal to the primary coil **106**, thereby inducing the secondary carrier signals on the secondary coils **108** of the sensor devices **104**.

As described above, the primary carrier signal is utilized as both a source of power and as a downlink/uplink carrier signal. To this end, the telemetry/power circuitry **150** further comprises a downlink modulator **154** configured for modulating the primary carrier signal with command data by varying the carrier signal at the primary coil **106** in accordance with the command data. Like the uplink modulator **142** in each of the sensor devices **104**, the downlink modulator **154** is an amplitude modulator that modulates the amplitude of the primary carrier signal, thereby allowing the sensor device **104** to acquire the command data as described above. The telemetry/power circuitry **150** further comprises an uplink demodulator **156** configured for demodulating the primary signal envelope at the primary coil **106** to acquire the EMG data (or status data) from the sensor devices **104**. The uplink demodulator **156** may acquire the EMG data from the primary carrier signal in a conventional manner by first detecting the modulated primary carrier signal envelope, and then comparing the detected envelope of the primary carrier signal to a threshold level that is preferably centered between a minimum and a maximum of the modulated primary carrier signal envelope.

For example, as shown in FIGS. **9a** and **9b**, the data (e.g., EMG data) can be serially received from the sensor devices **104(1)-104(n)** in an n number of dedicated time slots, respectively. As shown in FIG. **9a**, without using the aforementioned compensation technique, the primary carrier signal envelope P_{env} is not uniformly modulated for the sensor devices **104** over time slots t_1-t_n , such that multiple threshold levels $S_{th1}-S_{thn}$ must be used to acquire the data from the primary carrier signal envelope P_{env} . However, as shown in FIG. **9b**, using the aforementioned compensation technique, the primary carrier signal envelope is substantially uniformly amplitude modulated for the sensors devices **104** over time slots t_1-t_n , such that a single threshold level S_{th} may be used. As the primary carrier signal envelope crosses the threshold level S_{th} in one direction, a “1” or a “0” is detected (depending on the coding scheme), and as the primary carrier signal envelope crosses the threshold level S_{th} in the other direction, a “0” or a “1” is detected. Thus,

it can be appreciated that the demodulator **156** may utilize a simple comparator with a fixed threshold level to detect the uplink data. Although the primary carrier signal envelope is described as being amplitude modulated in accordance with an amplitude shift keying (ASK) technique, it should be appreciated that the primary carrier signal envelope may be amplitude modulated in accordance with other techniques, such as phase shift keying (PSK) and frequency shift keying (FSK) techniques.

The TC **102** further comprising a controller/processor **158** configured for controlling and operating the TC **102**, and processing the EMG data (raw or filtered) received from the sensor device **104**. The TC **102** further comprises an input/output interface **160**, such as a USB port, for communicating the processed EMG data to, and receiving commands, from the prosthetic controller **110** via the cable **112** (shown in FIG. 4). The TC **102** further comprises a power source **162**, e.g., a battery, for providing power to the circuitry of the TC **102**, and memory **164** configured for storing information, such as EMG data.

Referring now to FIG. 10, a detailed implementation of the telemetry/power circuitry **130** of the sensor device **104** will be described. In a conventional manner, the secondary coil **108** is represented by inductance L_s , and is combined in parallel with a capacitance C_s to form a receiver LC tank circuit that is inductively linked to corresponding transmitter LC tank circuit comprising the primary coil **106** and capacitance (not shown) at the TC **102**. The receiver LC tank circuit and transmitter LC tank circuit are tuned to resonant at the frequency of the carrier signal generated by the TC **102**, such that there is no parasitic reaction between the respective LC tank circuits.

The rectifier **132** is a conventional diode rectifier with cross-coupled NMOS transistors coupled across the receiver LC tank circuit to rectify the secondary carrier signal, and that delivers the rectified carrier signal to the regulator **134** for powering the circuitry. The positive portion of the secondary carrier signal is conducted through diode **D1** to the regulator **134**, while reverse biasing diode **D1** via transistor **M5**, and the negative portion of the secondary carrier signal is conducted through diode **D2** to the regulator **134**, while reverse biasing diode **D2** via transistor **M4**.

The amplitude detector **138** is coupled to the output of the rectifier **132** and includes a capacitor **C1** for detecting the peak amplitude of the rectified secondary carrier signal across the secondary coil **108**, and in this case, the amplitude of the unmodulated voltage V_{as} across the secondary coil **108** of the secondary carrier signal. The amplitude detector **138** is provided with a switch **S1** that can be opened or closed to selectively detect or not detect the unmodulated voltage amplitude V_{as} across the secondary coil **108**. The amplitude detector **138** is provided with a voltage buffer **139** for buffering the unmodulated voltage amplitude stored on the capacitor **C1** as V_{as} .

The processing circuitry **140** selects a modulating current I_c (which in the illustrated embodiment, is equivalent to a change in the load current ΔI_L) through the secondary coil **108** as a function of the measured unmodulated voltage V_{as} across the secondary coil **108** and stored in the voltage buffer **139**, such that the modulated envelope voltage V_{env} of the primary carrier signal on the primary coil **106** is substantially uniform for all of the sensor devices **104** communicating with the TC **102**. To this end, the processing circuitry **140** comprises a voltage-to-current converting circuit **144** configured for applying a dynamic function to the detected voltage V_{as} to output a modulating current I_c . The voltage-to-current converting circuit **144** may be a conventional

circuit known to provide a dynamic inverting function (i.e., as the input voltage increases, the output current decreases, and as the input voltage decreases, the output current increases), such as the function shown in FIG. 11. The voltage-to-current converting circuit **144** comprises a resistor R_b , which converts the unmodulated voltage amplitude V_{as} into the drain current I_6 of transistor **M6**. The voltage-to-current converting circuit **144** will produce an output current I_c , which is equal to $K \cdot I_b / I_6$, where K is a constant and I_b is a bias current inside the voltage-to-current converting circuit **144**. A supply voltage of V_{dd} is used to power the voltage-to-current converting circuit **144**. It should be appreciated that, although the voltage-to-current converting circuit **144** has been described as being analog in nature, the voltage-to-current converting circuit may be digital in nature. In this case, an analog-to-digital (A/D) converter can transform the analog detected voltage V_{as} to a digital voltage prior to input into the voltage-to-current converting circuit **144**, and a digital-to-analog (D/A) converter can transform the digital modulating current I_c into an analog current. A look-up table of voltage values and corresponding current values according to a dynamic inverting function, such as that shown in FIG. 11, can be stored in memory (not shown) as part of the digital voltage-to-current converting circuit **144**, which can be accessed by a digital processor.

The processing circuitry **140** further comprises current mirror circuitry **146** configured for applying the modulating current I_c output by the voltage-to-current converting circuit **144** to the secondary coil **108**, subject to the output of the modulator **142**, which takes the form of transistor **M3**. In particular, the current mirror circuitry **146** comprises a current mirror **M2-M1** coupled to the positive terminal of the secondary coil **104**, and a current mirror **M2-M0** coupled to the negative terminal of the secondary coil **104**.

Thus, when the transistor **M3** is switched off in response to an input of a particular bit value (e.g., a binary "1") from the uplink data stream, the modulating current I_c is passed through to the current mirror **M2-M1**, which mirrors the modulating current I_c to the positive terminal of the secondary coil **108**, resulting in a decrease in the positively polarized envelope of the voltage across the secondary coil **104**, as well as is passed through the current mirror **M2-M0**, which mirrors the modulating current I_c to the negative terminal of the secondary coil **108**, resulting in an increase in the negatively polarized envelope of the voltage across the secondary coil **104**. As a result, the voltage envelope V_{env} at the primary coil **104** is "low," indicating the particular bit value of "1." In contrast, when the transistor **M3** is switched on in response to an input of the other bit value (e.g., a binary "0") from the uplink data stream, the modulating current I_c is grounded through the transistor **M3**, and is therefore not passed through to the current mirrors **M2-M1** and **M2-M0**, resulting in no change to the positively polarized envelope or negatively polarized envelope of the voltage across the secondary coil **104**. As a result, the voltage envelope V_{env} at the primary coil **104** is "high," indicating the particular bit value of "0."

It should be noted that the voltage envelope V_{env} at the primary coil **104** can be made to be uniform without direct knowledge of the coupling coefficients K_c by defining the function between unmodulated voltage V_{as} and the modulating load current ΔI_L that achieves the uniform voltage envelope V_{env} . As an initial matter, for a fixed primary carrier signal applied to the primary coil **106**, as well as for fixed values for L_s , C_s , and R_s inside the sensor device **104**, the unmodulated voltage V_{as} across the secondary coil **108** only depends upon, and is typically proportional to, the

coupling coefficient K_c between the primary coil **106** and that secondary coil **108**. Since the envelope voltage V_{env} on the primary coil **106** depends on the coupling coefficient K_c and a modulating current I_c (e.g., a current through the secondary coil **108**), the envelope voltage V_{env} is a function of the coupling coefficient K_c and the modulating current I_c , and can be given as $V_{env}=f(K_c, I_c)$. Assume that the function $f(K_c, I_c)$ is separable and can be written as $g(K_c) \cdot h(I_c)$. Then, since the unmodulated voltage V_{as} across the secondary coil **108** is related to the coupling coefficient K_c , the envelope voltage V_{env} on the primary coil **108** can be further written as $V_{env}=G(V_{as}) \cdot h(I_c)$ by replacing the function $g(K_c)$ with the function $G(V_{as})$. To have a constant envelope voltage V_{env} on the primary coil **108** independent of the coupling coefficient K_c (and hence, the unmodulated voltage V_{as} across the secondary coil **108**), the function of $h(I_c)$ should be made proportional to the inverse of the function $G(V_{as})$, given as $G^{-1}(V_{as})$ with the modulating current I_c being a function of the unmodulated voltage V_{as} on the secondary coil **108**, given as $I_c=x(V_{as})$. Therefore, the envelope voltage V_{env} on the primary coil **108** can be written as: $V_{env}=g(K_c) \cdot h(I_c)=G(V_{as}) \cdot h(I_c)=G(V_{as}) \cdot G^{-1}(V_{as})=G(V_{as}) \cdot h(x(V_{as}))$, where $I_c=x(V_{as})$.

With this in mind, sensor devices **104** can be manufactured in a manner, such that the modulated signal envelope S_{env} on the primary coil **108** during uplink communication is substantially uniform across all of the sensor devices **104**. As a significant part of this manufacturing process, the dynamic inverting function illustrated in FIG. **11** can be customized to the specific primary coil **106** and secondary coil **108** of the respective telemetry controller **102** and sensor device **104** to be manufactured, so that the sensor devices **104** can load modulate the secondary carrier signals on the respective secondary coils **108** that more accurately results in a substantially uniform modulated signal envelope S_{env} on the primary coil **108**.

For example, one method **200** of manufacturing the sensor device **104** will be described with respect to FIG. **12**. First, the primary coil L_p and the secondary coil L_s , respectively corresponding to the primary coil **106** that will be used in the telemetry controller **102** and the secondary coil **108** that will be used in each of the sensor devices **104**, are provided (step **202**). Actual versions of the primary coil L_p and the secondary coil L_s may be provided, or alternatively, the primary coil L_p and the secondary coil L_s may be simulated. Next, a uniform value (e.g., a uniform voltage value M_{env}) for an amplitude modulation induced on the primary coil L_p is selected (step **204**). In the illustrated embodiment, the uniform value for the amplitude modulation induced on the primary coil L_p is selected to be the minimum value expected between the corresponding primary coil **106** and secondary coil **108**, assuming the worst-case functioning coupling coefficient K_c . Next, a coupling coefficient value K_c is selected between the primary coil L_p and the secondary coil L_s (step **206**). In the illustrated embodiment, the expected worst-case value of the coupling coefficient K_c is selected.

Next, a primary alternating current (AC) signal having a fixed value (e.g., fixed current value) is applied to the primary coil L_p , thereby respectively inducing a secondary signal on the secondary coil L_s for the coupling coefficient value K_c (step **208**). The amplitude of the secondary signal (e.g., the peak voltage amplitude) is then determined (step **210**). Next, the amplitude of a modulating signal (e.g., a signal that defines a change in the current within the secondary coil **208**) for modulating an envelope of the secondary signal is determined, such that it induces an amplitude

modulation on the primary coil L_p that is substantially equal to the uniform amplitude modulation value selected in step **202** (step **212**). In one method, the amplitude of the modulating signal is determined by adjusting the modulating signal until the amplitude modulation induced on the primary coil L_p is substantially equal to the selected uniform amplitude modulation value. It should be appreciated that steps **208-212** can be performed in an actual environment, in which case, the amplitude of the secondary signal on the secondary coil L_s at step **210** and the amplitude modulation on the primary coil L_p at step **212** can be measured, or steps **218-212** can be performed in a simulated environment, in which case, the amplitude of the secondary signal on the secondary coil L_s at step **210** and the amplitude modulation on the primary coil L_p at step **212** can be computed.

Next, the determined amplitudes of the secondary signal and modulating signal are correlated to create a data point (step **214**), and steps **206-214** are repeated for different coupling coefficient values using the same fixed value for the primary signal that is applied to the primary coil L_p , as well as the same values for the inductance L_s , capacitance C_s , and load resistance R_s , thereby creating another data point. Steps **206-214** are repeated until a sufficient number of data points are created. In the illustrated embodiment, steps **206-214** are repeated for incrementally increasing coupling coefficients K_c . If a sufficient number of data points are created, e.g., when the expected best-case value of the coupling coefficient K_c is reached (step **216**), a relationship between the respective amplitudes of the secondary signal and modulating signal is derived from the data points, which relationship represents the amplitudes of the secondary signal and modulating signal that maintains the uniform envelope signal M_{env} on the primary coil L_p (step **218**). Such a relationship may, e.g., have a shape resembling the function illustrated in FIG. **11**. Lastly, the sensor device **104** is manufactured with the secondary coil L_s , an amplitude detector configured for measuring the amplitude of a secondary carrier signal induced on the secondary coil, and processing circuitry configured for outputting a modulating signal in response to an input of the measured amplitude of the secondary carrier signal in accordance with the derived relationship, such that an envelope of the secondary carrier signal is load modulated (step **220**). The processing circuitry may be analog in nature, such as the processing circuitry **144** illustrated in FIG. **10**, in which case, the processing circuitry **144** may be tuned or calibrated in accordance with the data values generated in step **214**, or the processing circuitry may be digital in nature, in which case, the data points generated in step **214** can be used to create a look-up table for storage in memory that can be subsequently accessed by the digital processing circuitry.

Although the relationship between the respective amplitudes of the secondary signal and the modulating signal is described as being derived from the data points generated in steps **202-218** for purposes of ensuring that the relationship is as accurate as possible for a particular geometry of the coils primary coil L_p and secondary coil L_s , it should be appreciated that in a simplified method, the relationship between the respective amplitudes of the secondary signal and the modulating signal can roughly be approximated from the function illustrated in FIG. **11**.

Thus, it can be appreciated that the envelope signal (such as the envelope voltage V_{env}) induced on the primary coil **106** of the TC **102** when receiving uplink data from different sensor devices **104** with different coupling coefficients K_c will be automatically adjusted to a uniform value (e.g., uniform envelope voltage M_{env}).

Having described the structure and function of the prosthetic control system **100**, one method **300** of operating the prosthetic control system **100** to power the implanted sensor devices **104** (and in this case, sensor devices **104**) and communicate physiological data, and in this case EMG data) of the patient **50** from the implanted sensor devices **104** to the TC **102** of the prosthetic control system **100** will be described with respect to FIGS. **10** and **13**.

First, a primary alternating current (AC) carrier signal having an envelope is applied to the primary coil **106** of the TC **102**, thereby respectively inducing a secondary carrier signal having an envelope on each of the secondary coils **108** of the respective implanted sensor devices **104** (step **302**). The rectifier **132** rectifies the respective secondary carrier signal, and the regulator **134** regulates and supplies the power to the circuitry of each of the sensor devices **104** (step **304**). Next, each of the sensor devices **104** generates data, e.g., by acquiring EMG data from adjacent muscles of the patient **50** via the respective electrodes **120** (step **306**). Next, the amplitude of the secondary carrier signal (e.g., the peak voltage) on the secondary coil **108** of each of the sensor devices **104** is measured by the respective amplitude detector **138** (step **308**). Notably, the amplitude of the secondary carrier signal is preferably measured, when unmodulated, and not measured during modulation. As such, measurement of the amplitude of the secondary carrier signal can be selectively performed by closing the switch **S1** in the amplitude detector **138**. Once such amplitude is measured, the switched **S1** can be opened to essentially disconnect the amplitude detector **138** from the processing circuitry **140**.

Next, in response to the measured amplitude of the unmodulated secondary carrier signal, the processing circuitry **140** of each sensor device **104** generates a modulating signal (e.g., a change in the current through the secondary coil **108**) (step **310**). Then, the uplink modulator **142** of each sensor device **104** serially load modulates the envelope of the secondary carrier signal on the respective secondary coil **108** in accordance with the data by selectively applying the modulation signal to the secondary coil **108** (i.e., applying the modulation signal to the secondary coil **108** in response to a "1" or "0" depending on the coding scheme) and not applying the modulation signal to the secondary coil **108** in response to the other of "1" or "0"), thereby inducing an amplitude modulation of the primary carrier signal envelope on the primary coil **106** (step **312**).

The amplitude of the modulation signal generated by the processing circuitry **140** of each sensor device **104** is such that the variation of the amplitude modulation of the primary carrier signal envelope between sensor devices **104** is decreased relative to a variation between the coupling coefficients K_c , thereby compensating for the different coupling coefficients K_c between the primary coil **106** and the respective secondary coils **108**. The amplitude modulation of the primary carrier signal envelope between the sensor devices **104** may be substantially uniform (e.g., less than 50% variation, and preferably less than 20% variation). For example, each of the secondary carrier signal envelopes is load modulated, such that the modulation magnitudes of the load modulated secondary carrier signal envelopes on the secondary coils **108** varies in an inversely varying relationship with the measured unmodulated carrier signal amplitudes (and thus, the respective coupling coefficients K_c) on the secondary coils **108**.

Lastly, the uplink demodulator **156** of the TC **102** demodulates the modulated primary carrier signal envelope on the primary coil **106** to sequentially acquire the data from the sensor devices **104** (step **314**). In the illustrated embodi-

ment, the uplink demodulator demodulates the modulated primary carrier signal by detecting the modulating primary carrier signal envelope, and comparing it to the threshold level centered between a minimum and a maximum of the modulated primary carrier signal envelope.

Although particular embodiments of the present inventions have been shown and described, it will be understood that it is not intended to limit the present inventions to the preferred embodiments, and it will be obvious to those skilled in the art that various changes and modifications may be made without departing from the spirit and scope of the present inventions. Thus, the present inventions are intended to cover alternatives, modifications, and equivalents, which may be included within the spirit and scope of the present inventions as defined by the claims.

What is claimed is:

1. An implantable medical device for communicating with a telemetry controller having a primary coil on which a primary carrier signal is applied, comprising:

a secondary coil on which a secondary carrier signal having an envelope may be induced in response to the application of the primary carrier signal on the primary coil;

an amplitude detector configured for measuring a voltage of the secondary carrier signal across the secondary coil;

a voltage-to-current converting circuit configured for selecting a magnitude of a modulation of the secondary carrier signal by converting the measured voltage of the secondary carrier signal to a load current associated with the secondary coil in accordance with an inversely varying relationship with the measured voltage of the secondary carrier signal; and

a modulator configured for applying the selected modulation magnitude to the secondary carrier signal envelope by modulating the load current in accordance with data, thereby inducing an amplitude modulation of an envelope of the primary carrier signal.

2. The implantable medical device of claim 1, wherein the measured voltage of the secondary carrier signal comprises a peak voltage of the secondary carrier signal.

3. The implantable medical device of claim 1, wherein the voltage-to-current converting circuit is an analog voltage-to-current converting circuit.

4. The implantable medical device of claim 1, further comprising a rectifier configured for rectifying and regulating the secondary carrier signal for powering circuitry within the implantable medical device.

5. The implantable medical device of claim 1, further comprising a biocompatible casing containing the secondary coil, amplitude detector, voltage-to-current converting circuit, and modulator.

6. The implantable medical device of claim 1, wherein the voltage-to-current converting circuit is a digital voltage-to-current converting circuit, the implantable medical device further comprising an analog-to-digital (A/D) converter configured for converting the measured voltage of the secondary carrier signal into a digital voltage value for input into the digital voltage-to-current converting circuit, and a digital-to-analog (D/A) converter configured for converting a digital current value output by the digital voltage-to-current converting circuit into the load current.

7. The implantable medical device of claim 1, wherein the data is physiological data of a patient, the implantable medical device further comprising at least one sensor configured for acquiring the physiological data from the patient.

8. The implantable medical device of claim 1, wherein the data is operational status data of the implantable medical device.

9. A method of communicating between a telemetry controller and a medical device implanted within a patient, the telemetry controller having a primary coil, and the medical device having a secondary coil, the method comprising:

generating data by the implanted medical device;
applying a primary carrier signal having an envelope to the primary coil, thereby respectively inducing a secondary carrier signal having an envelope on the secondary coil;

measuring a voltage of the secondary carrier signal across the secondary coil;

selecting a magnitude of a modulation of the secondary carrier signal by converting the measured voltage of the secondary carrier signal to a load current associated with the secondary coil in accordance with an inversely varying relationship with the measured voltage of the secondary carrier signal;

applying the selected modulation magnitude to the secondary carrier signal envelope by modulating the load current in accordance with the data generated by the implanted medical device, such that the primary carrier signal envelope is amplitude modulated; and

amplitude demodulating the modulated primary carrier signal envelope to acquire the data from the implanted medical device.

10. The method of claim 9, wherein the telemetry controller is external to the patient.

11. The method of claim 9, wherein the measured voltage of the secondary carrier signal comprises a peak voltage of the secondary carrier signal.

12. The method of claim 9, wherein amplitude demodulating the modulated primary carrier signal envelope comprises:

detecting the modulated primary carrier signal envelope;
and

comparing the detected modulated primary carrier signal envelope to a threshold level.

13. The method of claim 12, wherein an amplitude of the threshold level is between a minimum and a maximum of the modulated primary carrier signal envelope.

14. The method of claim 13, wherein the amplitude of the threshold level is centered between the minimum and the maximum of the modulated primary carrier signal envelope.

15. The method of claim 9, wherein the measured voltage is converted to the load current in an analog fashion.

16. The method of claim 9, wherein converting the measured voltage of the secondary carrier signal to a load current comprises transforming the measured voltage of the secondary carrier signal into a digital voltage value, converting the digital voltage value into a digital current value, and transforming the digital current value into the load current.

17. The method of claim 9, wherein the generated data is physiological data acquired from the patient by the implantable medical device.

18. The method of claim 9, wherein the generated data is operational status data of the implantable medical device.

19. A method of manufacturing an implantable medical device, comprising:

(a) selecting a uniform value for an amplitude modulation induced on a primary signal envelope;

(b) selecting a coupling coefficient value between a primary coil and a secondary coil;

(c) applying a fixed alternating current (AC) signal to the primary coil, thereby respectively inducing a secondary signal on the secondary coil for the selected coupling coefficient value;

(d) determining an amplitude of the secondary signal for the coupling coefficient value;

(e) determining an amplitude of a modulating signal for modulating an envelope of the secondary signal in a manner that induces an amplitude modulation on the primary coil that is substantially equal to the selected uniform amplitude modulation value;

(f) correlating the determined amplitude of the secondary signal and the determined amplitude of the modulating signal to create a data point;

(g) repeating steps (b)-(f) for different coupling coefficient values to create a plurality of data points;

(h) deriving a relationship between the respective amplitudes of the secondary signal and the modulating signal from the plurality of data points; and

(i) manufacturing the implantable medical device having the secondary coil and processing circuitry configured for outputting the modulating signal in response to an input of a measured amplitude of a secondary carrier signal induced on the secondary coil in accordance with the derived relationship, such that an envelope of the secondary carrier signal is modulated.

20. The method of claim 19, wherein the amplitude of the modulating signal is determined by adjusting the modulating signal until the amplitude modulation induced on the primary signal envelope is substantially equal to the selected uniform amplitude modulation value.

21. The method of claim 19, wherein steps (c)-(e) are simulated.

22. The method of claim 19, wherein steps (c)-(e) are actually performed.

23. The method of claim 19, wherein the determined amplitude of the secondary signal comprises a peak amplitude of the secondary signal.

24. The method of claim 19, wherein determining the amplitude of the secondary signal on the secondary coil comprises determining a voltage across the secondary coil, and wherein the modulating signal defines a change in a current in the secondary coil.